



# *PCI Express 3.0 Overview*

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*Intel Corp.*

*HotChips - Aug 23, 2009*



# Agenda

- **PCIe Architecture Overview**
- **PCIe 3.0 Electrical Optimizations**
- **PCIe 3.0 PHY Encoding and Challenges**
- **New PCIe Protocol Features**
- **Summary & Call to action**

# PCI Express\* (PCIe) Interconnect

## Physical Interface

- Point-to-point full-duplex
- Differential low-voltage signaling
- Embedded clocking
- Scalable width & frequency
- Supports connectors and cables

## Protocol

- Load Store architecture
- Fully packetized split-transaction
- Credit-based flow Control
- Virtual Channel mechanism

## Advanced Capabilities

- Enhanced Configuration and Power Management
- RAS: CRC Data Integrity, Hot Plug, Advanced error logging/ reporting
- QoS and Isochronous support

## IO Trends

- Increase in IO Bandwidth
- Reduction in Latency
- Energy Efficient Performance

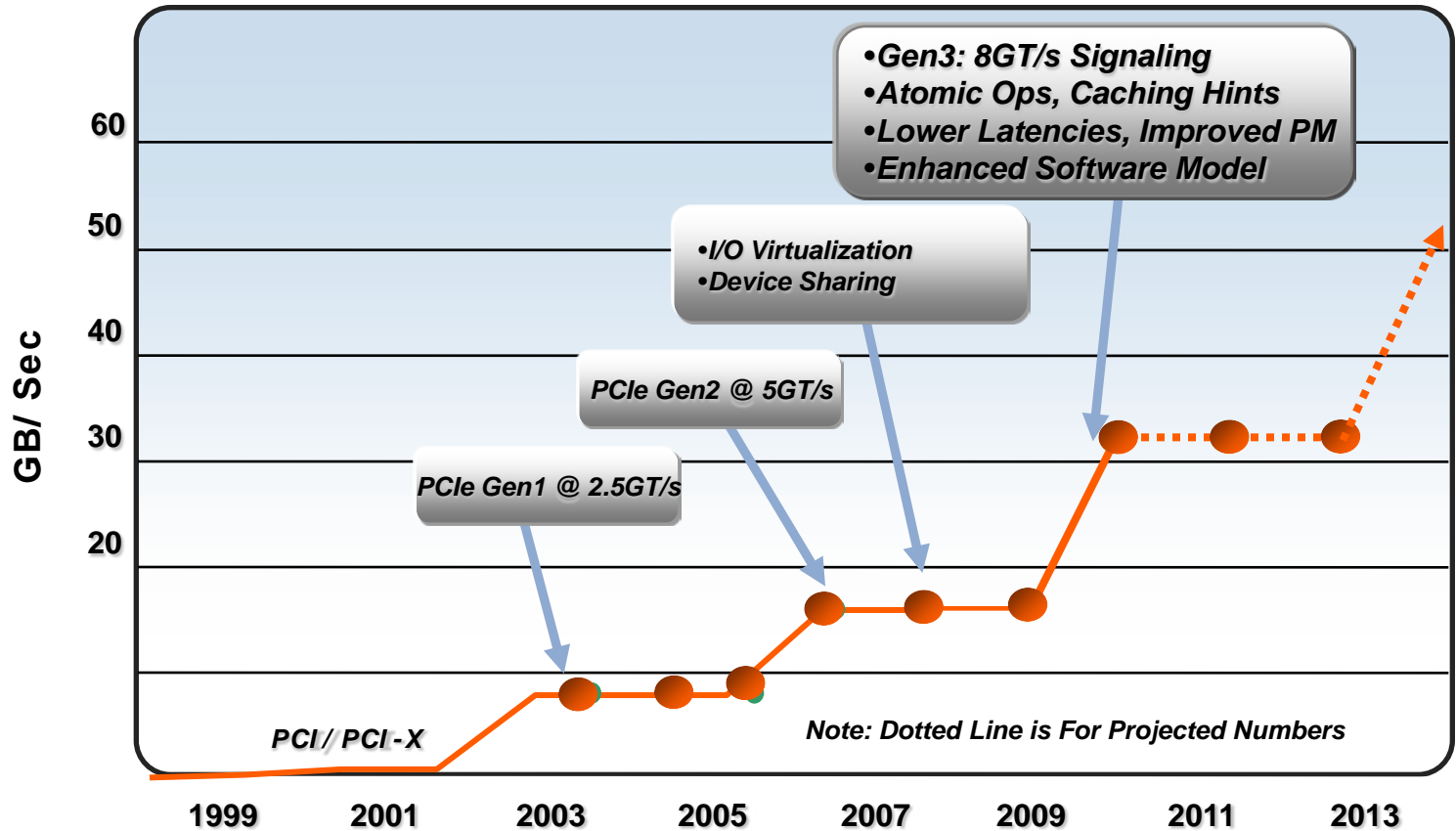
## Emerging Applications

- Virtualization
- Optimized Interaction between Host & IO
- Examples: Graphics, Math, Physics, Financial & HPC Apps.

*New Generations of  
PCI Express Technology*



# PCIe Technology Roadmap



	Raw Bit Rate	Link BW	BW/lane/way	BW x16
PCIe 1.x	2.5GT/s	2Gb/s	~ 250MB/s	~ 8GB/s
PCIe 2.0	5.0GT/s	4Gb/s	~ 500MB/s	~ 16GB/s
PCIe 3.0	8.0GT/s	8Gb/s	~ 1GB/s	~ 32GB/s

Based on x16 PCIe channel

All dates time frames and products are subject to change without further notification

**Continuous Improvement: Doubling Bandwidth & Improving Capabilities Every 3-4 Years!**

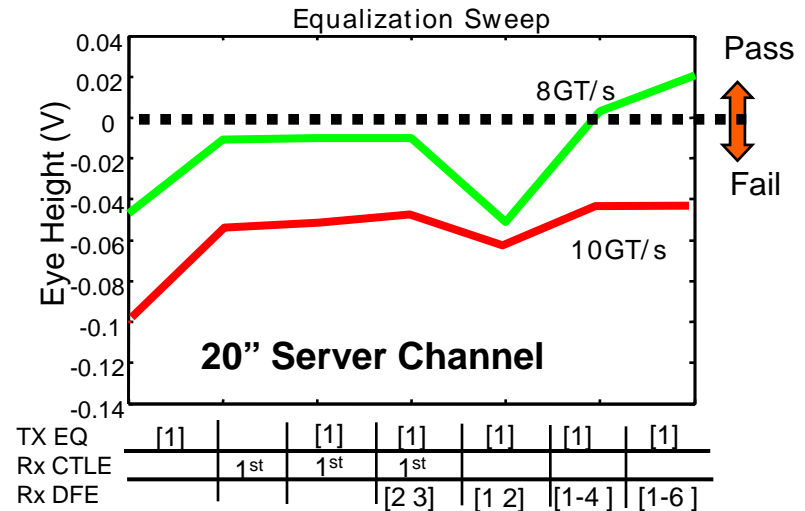
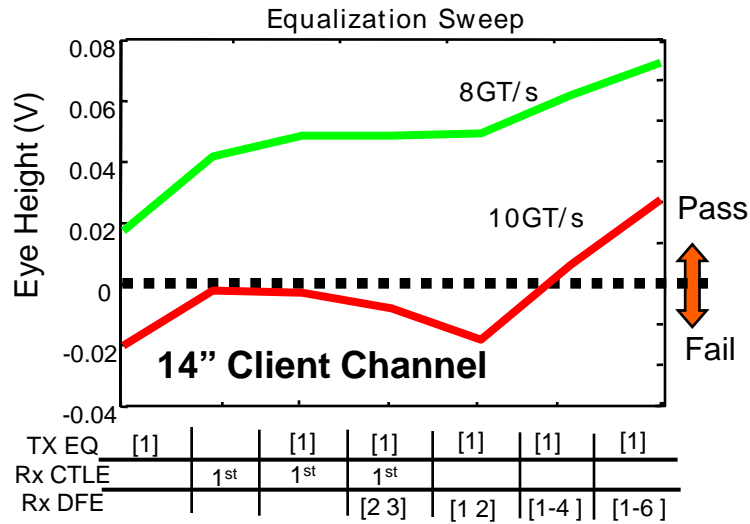


# PCI e 3.0 Electrical Interface

# PCIe 3.0 Electrical Requirements

- **Compatibility with PCIe 1.x, 2.0**
- **2x payload performance bandwidth over PCIe 2.0**
- **Similar cost structure (i.e. no significant cost adders)**
- **Preserve existing data clocked and common clock architecture support**
- **Maximum reuse of HVM ingredients**
  - FR4, reference clocks, etc.
- **Strive for similar channel reach in high-volume topologies**
  - Mobile: 8", 1 connector
  - Desktop: 14", 1 connector
  - Server: 20", 2 connectors

# PCIe Gen3 Solution Space



Source: Intel Corporation

- **Solution space exists to satisfy 8GT/ s client and server channels requirements**
  - Power, channel loss and distortion much worse at 10GT/s
  - Similar findings by PCI-SIG members corroborated Intel analysis
- **PCI-SIG approved 8GT/ s as PCIe 3.0 bit rate**

CTLE= Continuous Time Linear Equalizer  
DFE= Decision Feedback Equalizer





# Enabling Factors for 8G

- **Scrambling permits 2x payload rate increase wrt. Gen2 with 8 GT/s data rate**
  - Scrambling eliminates 25% coding overhead of 8b/10b
  - 8G chosen over 10G due to eye margin considerations
- **More capable Tx de-emphasis**
  - One post cursor tap and one pre cursor tap (2.5 and 5G has 1 post cursor tap)
  - Six selectable presets cover most equalization requirements
  - Finer Tx equalization control available by adjusting coefficients
- **Receiver equalization**
  - 1<sup>st</sup> order LE (linear eq.) is assumed as minimum Rx equalization
  - Designs may implement more complex Rx equalization to maximize margins
  - Back channel allowing Rx to select fine resolution Tx equalization settings
- **BW optimizations for Tx, Rx PLLs and CDR**
  - PLL BW reduced, CDR (Clock Data Recovery) jitter tracking increased
  - CDR BW > 10 MHz, PLL BW 2-4 MHz



# PCI e 3.0 Encoding/ Signaling

# Problem Statement

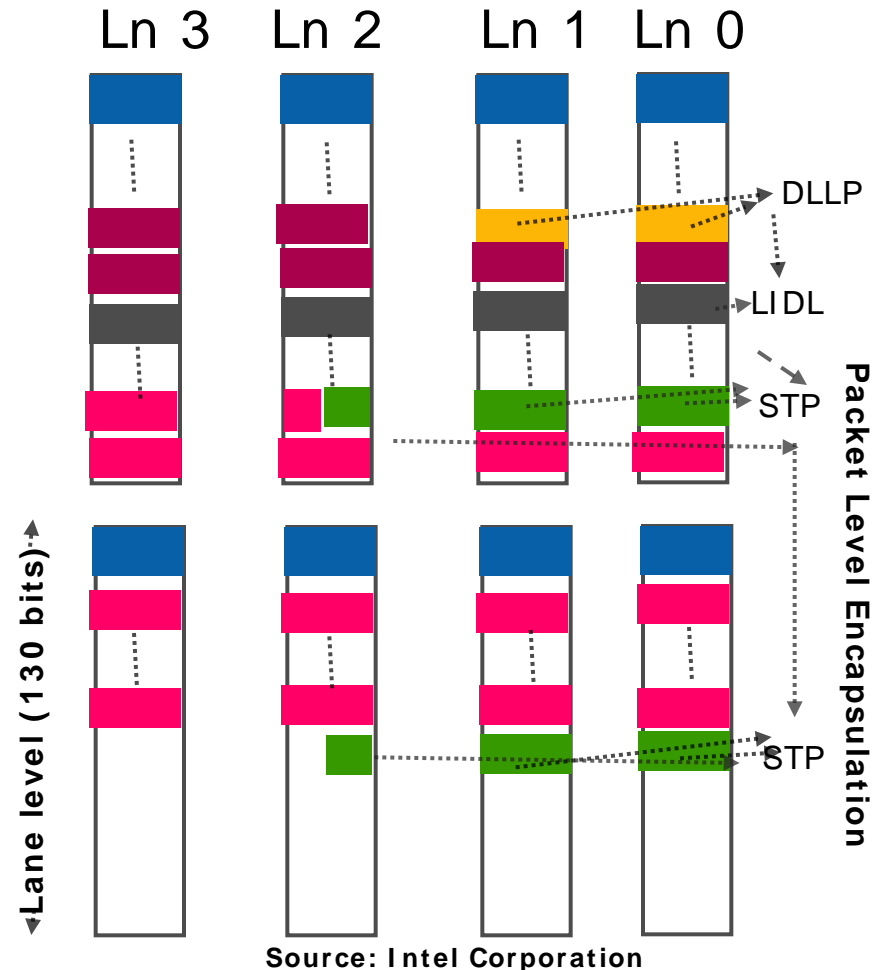
- **PCI Express\* (PCIe) 3.0 data rate decision: 8 GT/s**
  - High Volume Manufacturing channel for client/ servers
    - Same channels and length for backwards compatibility
    - Low power and ease of design - avoid using complicated receiver equalization, etc.
- **Requirement: Double Bandwidth from Gen 2**
  - PCIe 1.0a data rate: 2.5 GT/s
  - PCIe 2.0 data rate: 5 GT/s
    - Doubled the bandwidth from Gen 1 to Gen 2 by doubling the data rate
  - Data rate gives us a 60% boost in bandwidth
  - Rest will come from **Encoding**
    - Replace 8b/10b encoding with a scrambling-only encoding scheme when operating at PCIe 3.0 data rate
- **Double B/ W: Encoding efficiency 1.25 X data rate 1.6 = 2X**

***Challenge: New Encoding Scheme to cover  
256 data plus 12 K-codes with 8 bits***



# New Encoding Scheme

- Two levels of encapsulation
  - Lane Level (mostly 128/130)
  - Packet Level to identify packet boundaries
    - Point to where next packet begins
- Additive Scrambling only (no 8b/10b) to provide edge density
  - Data Packets scrambled
    - TLP/ DLLP/ LIDL
  - Ordered Sets mostly not scrambled
  - Electrical Idle Exit Ordered Set resets scrambler (Recovery/ Config)



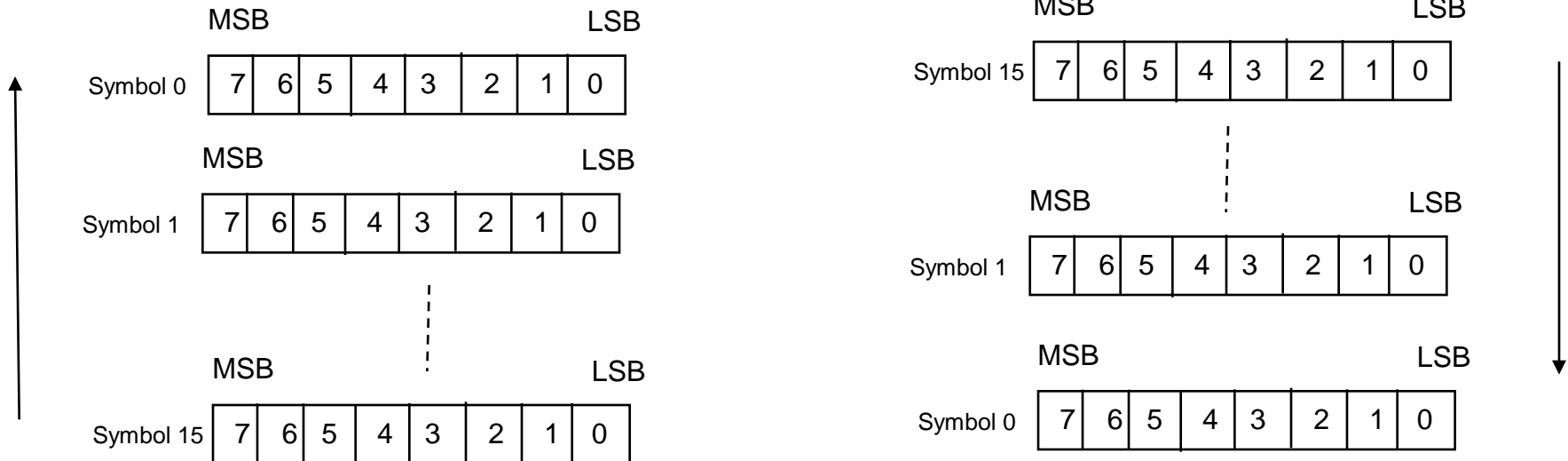
**Scrambling with two levels of encapsulation**



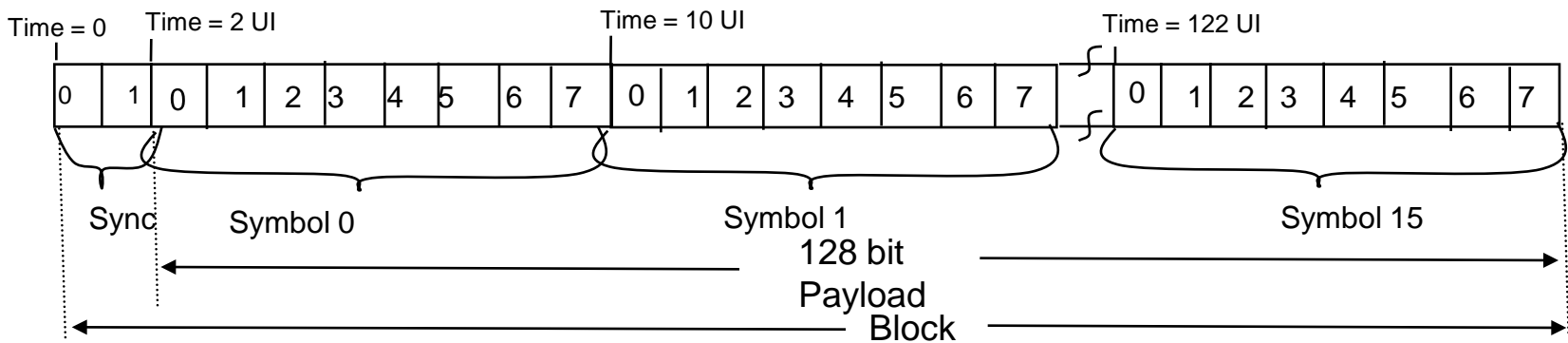
# Mapping of bits on a x1 Link

Receive

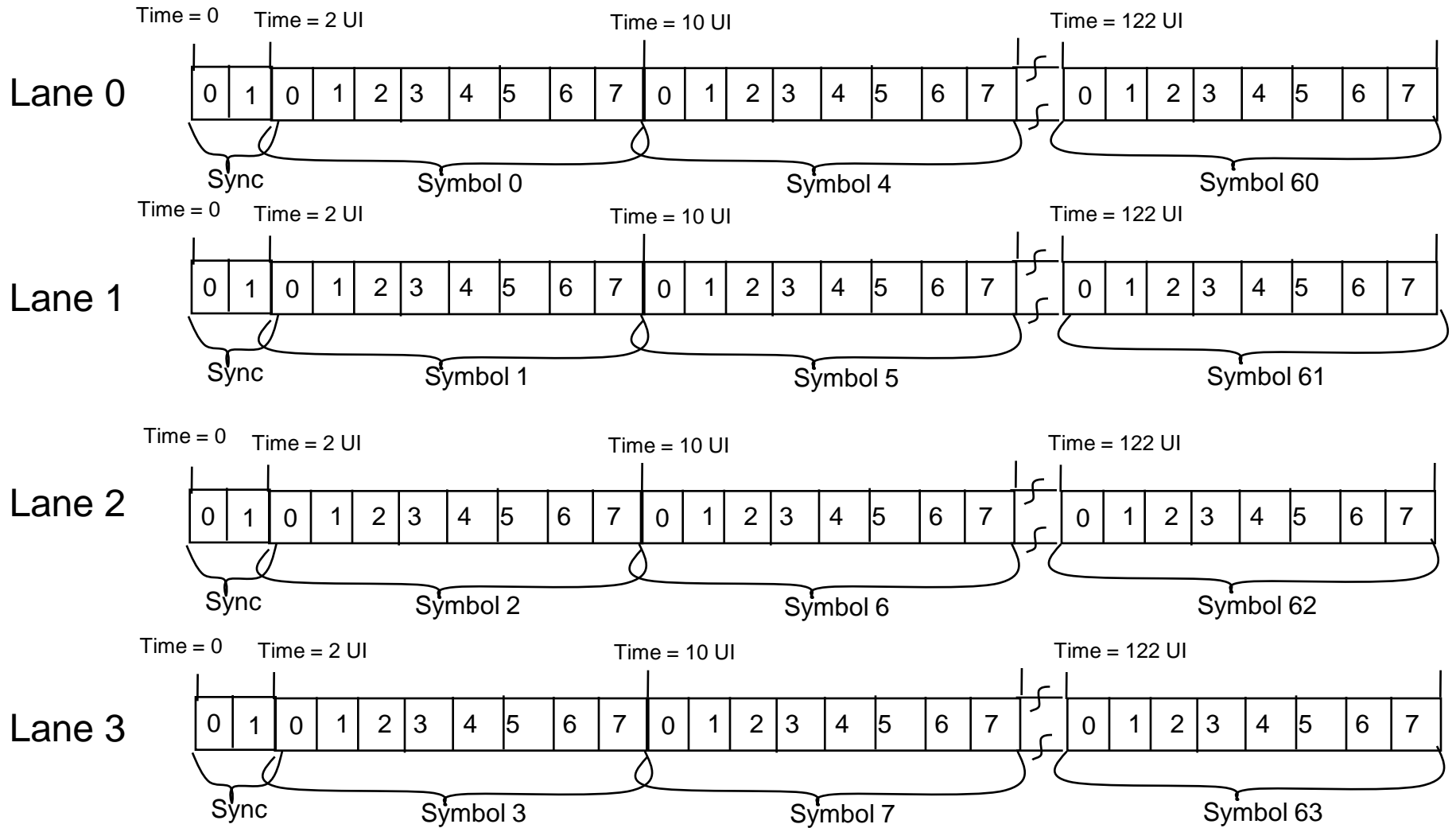
Transmit



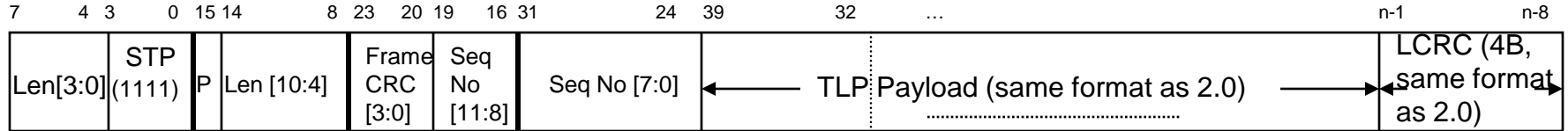
X1 Link



# Mapping of bits on a x4 Link



# P-Layer Encapsulation: TLP



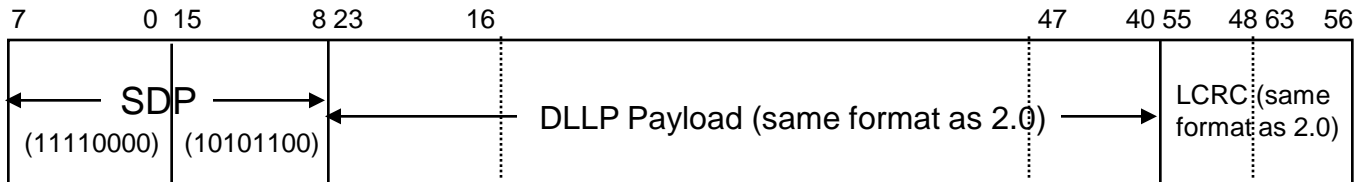
[Len[10:0]: length of the TLP in DWs, Frame CRC[4:0]: Check Bits covering Length[0:10], P: Frame Parity, No END]

- **Length known from the first 3 Symbols**
  - First 4 bits are 1111 (bit[0:3] = 4'b1111)
  - Bits 4:14 has the length of the TLP (valid values: 5 to 1031)\*
  - Bits 15 and 20:23 is check bits to cover the TLP Length field
    - Primitive Polynomial ( $X^4 + X + 1$ ) protects 15 bit field
      - Provides double bit flip detection guarantee (length 11 bits + CRC 4 bits)
      - Odd parity covers the 15 bits (length 11 bits + CRC 4 bits)
        - Guaranteed detection of triple bit errors (over 16 bits)
- **Sequence Number occupies bits 16:19 and 24:31**
- **TLP payload is from the 4th Symbol position (same as 2.0)**
- **No explicit END - Check 1st Symbol after TLP for implicit END vs. an explicit EDB => Ensures triple bit flip detection**
- **All Symbols are scrambled/ de-scrambled**

\*Note: Valid values for a TLP Prefix is 5 to ~ 1039 (Max value depends on type of TLP Prefix)



# P-Layer Encapsulation: DLLP

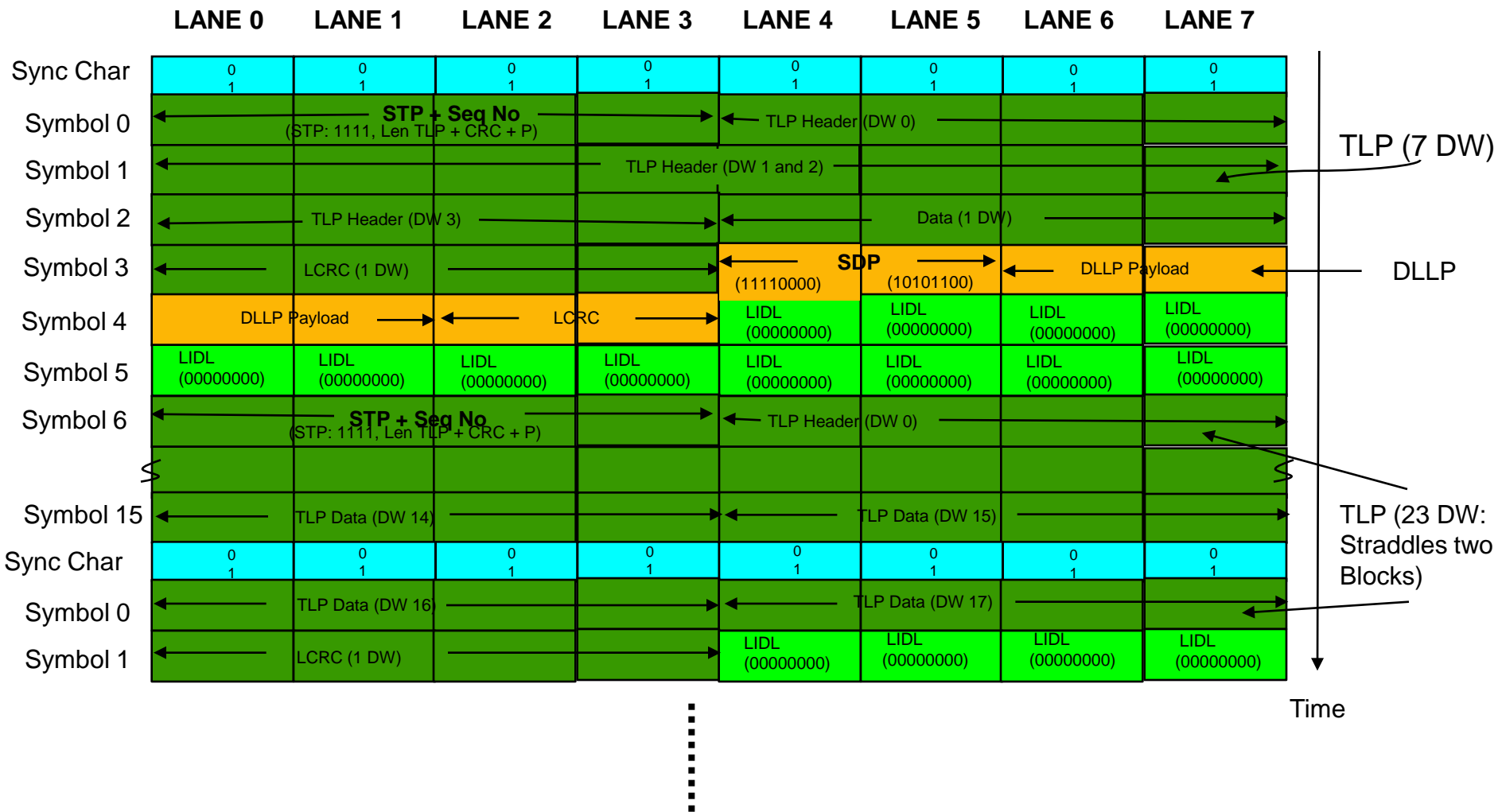


(DLLP Layout)

- **Preserve DLLP layout of 2.0 spec**
- **First Symbol is F0h**
- **Second Symbol is ACh**
- **Next 4 Symbols (2 through 5) are the DLLP layout**
- **Next 2 Symbols (6 and 7): LCRC (identical to 2.0)**
- **No explicit END**
- **All Symbols are scrambled/ de-scrambled**



# Ex: TLP/ DLLP/ IDLs in x8



⋮

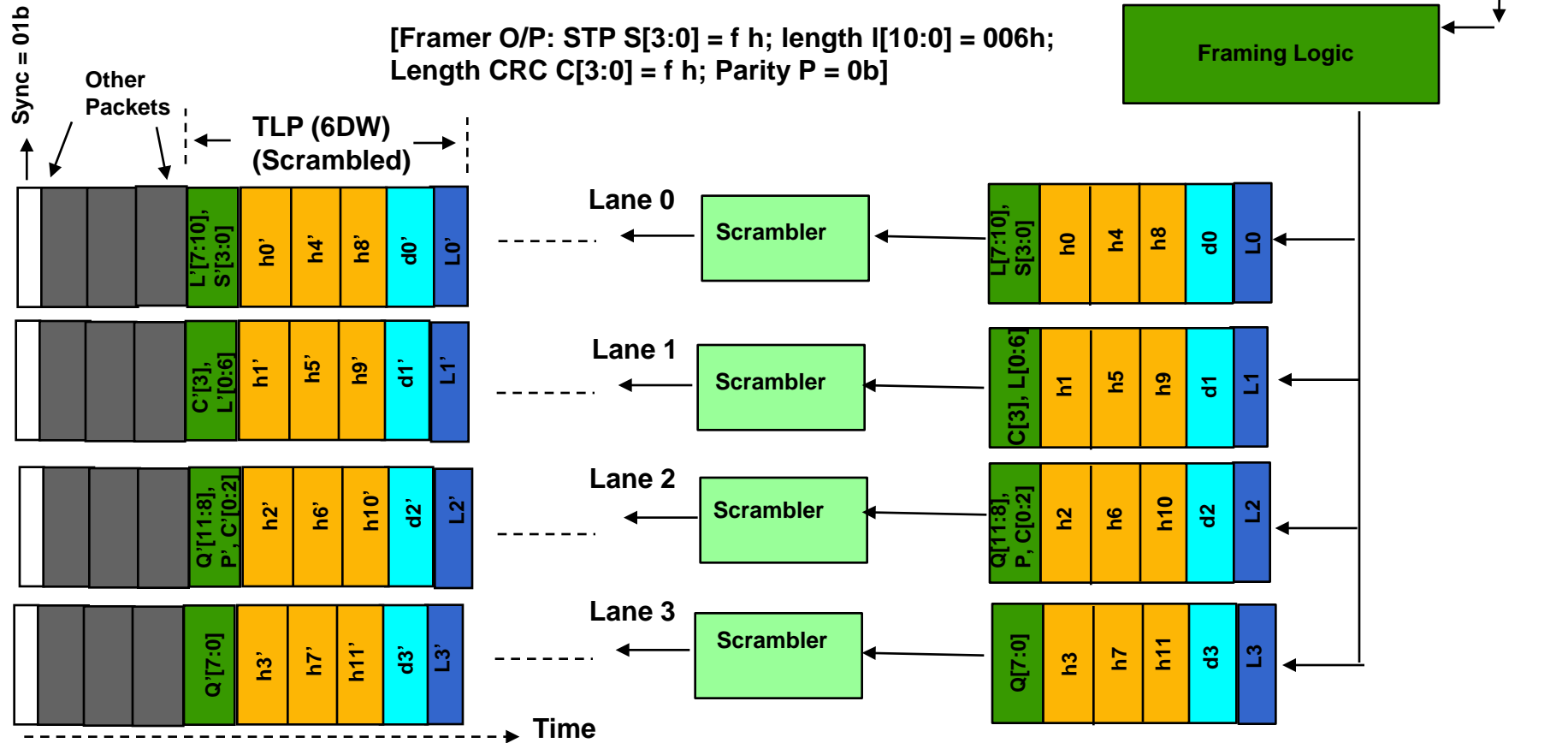


# TLP Transmission in a X4 Link



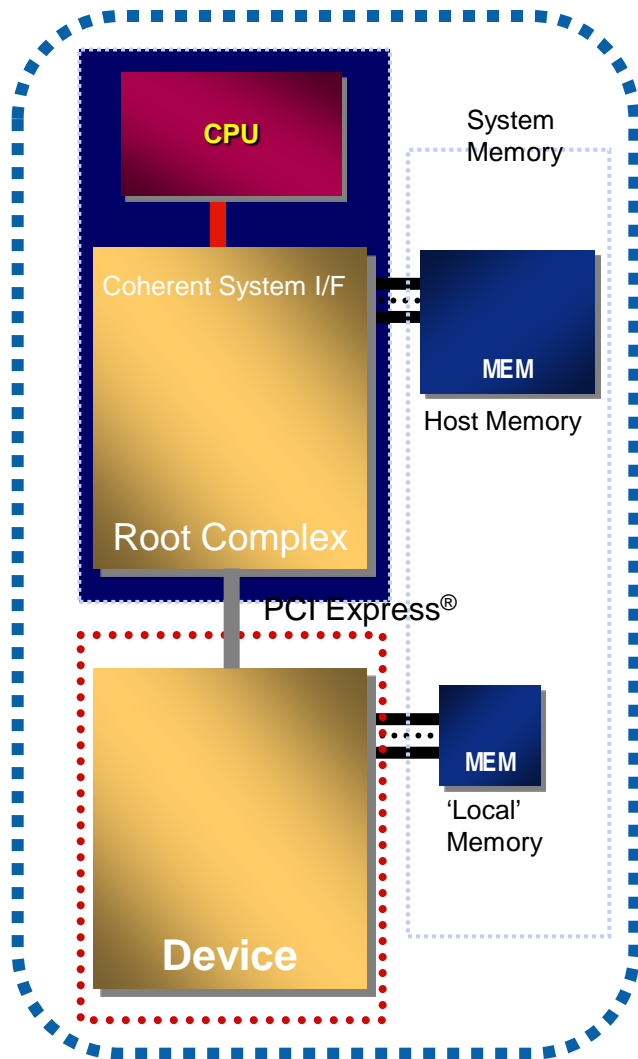
(TLP Transmitted: 3 DW Header (h0 .. h11) + 1 DW Data (d0 .. D3).  
1 DW LCRC (L0 .. L3) and Q[11:0]: Sequence No from Link Layer)

[Framer O/P: STP S[3:0] = f h; length I[10:0] = 006h;  
Length CRC C[3:0] = f h; Parity P = 0b]



# PCIe 3.0 Protocol Extensions

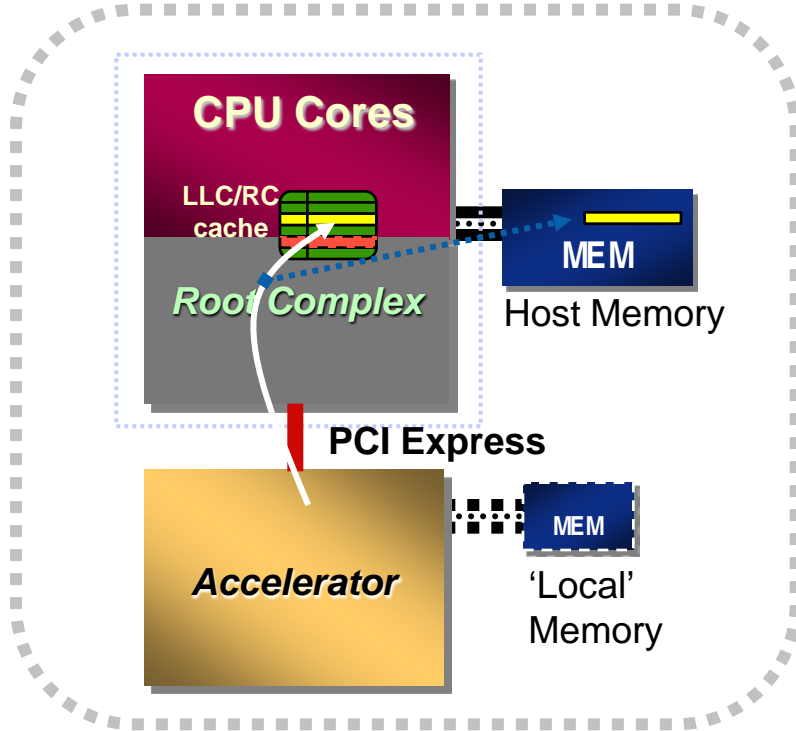
# Protocol Extensions



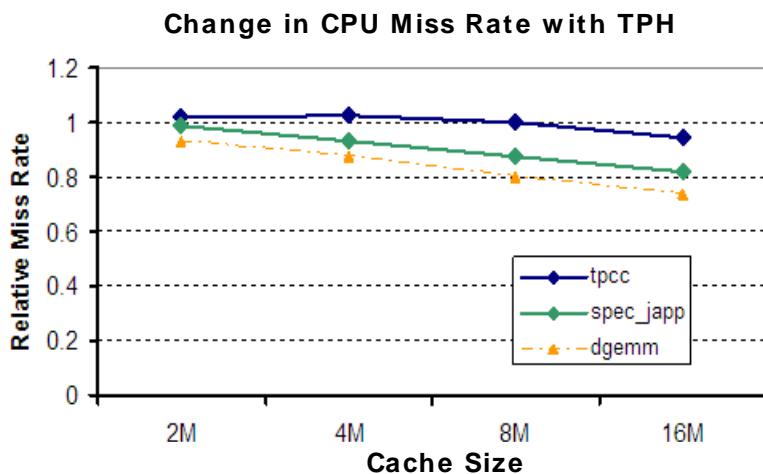
- **Performance Improvements**
  - **TLP Processing Hints** – hints to optimize system resources and performance
  - **TLP Prefix** – mech to extend TLP headers for TLP Processing Hints, MR-IOV, and future extensions
  - **ID-Based Ordering** – Transaction-level attribute/hint to optimize ordering within RC and memory subsystem
  - **Extended Tag Enable Default** – permits default for Extended Tag Enable bit to be Function-specific
- **Software Model Improvements**
  - **Atomic Operations** – new atomic transactions to reduce synchronization overhead
  - **Page Request Interface** – mech in ATS 1.1 for a device to request faulted pages to be made available (not covered)
- **Communication Model Enhancements**
  - **Multicast** – mechanism to transfer common data or commands sent from one source to multiple recipients
- **Power Management**
  - **Dynamic Power Allocation** – support for dynamic power operational modes through standard configuration mech
  - **Latency Tolerance Reporting** – Endpoints report service latency requirements for improved platform power mgmt
  - **Optimized Buffer Flush/ Fill** – Mechs for devices to align DMA activity for improved platform power mgmt
- **Configuration Enhancements**
  - **Resizable BAR**– Mechanism to support BAR size negotiation
  - **Internal Error Reporting**– Extend AER to report component internal errors and record multiple error logs

# TLP Processing Hints (TPH)

# Transaction Processing Hints

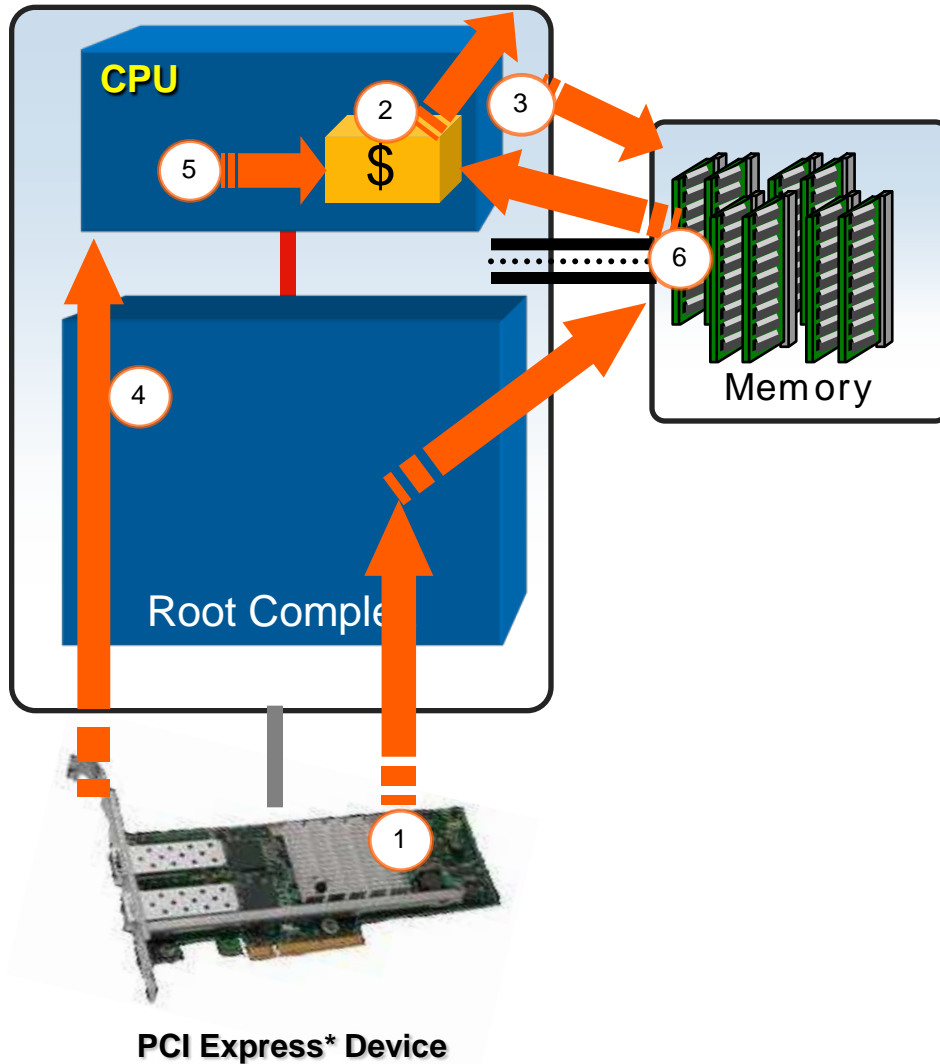


- Background:
  - **Small IO Caches implemented in server platforms**
    - Ineffective w/o info about intended use of IO data
- Feature:
  - **TPH= hints on a transaction basis**
    - Allocation & temporal reuse
  - **More direct CPU<-> IO collaboration**
    - Control structures (headers, descriptors) and data payloads
- Benefits:
  - **Reduced access latencies**
    - Improved data retention/allocation
  - **Reduced mem & QPI BW/ power**
    - Avoiding data copies
  - **New applications**
    - Comm adapters for HPC and DB clusters, Computational Accelerators,...

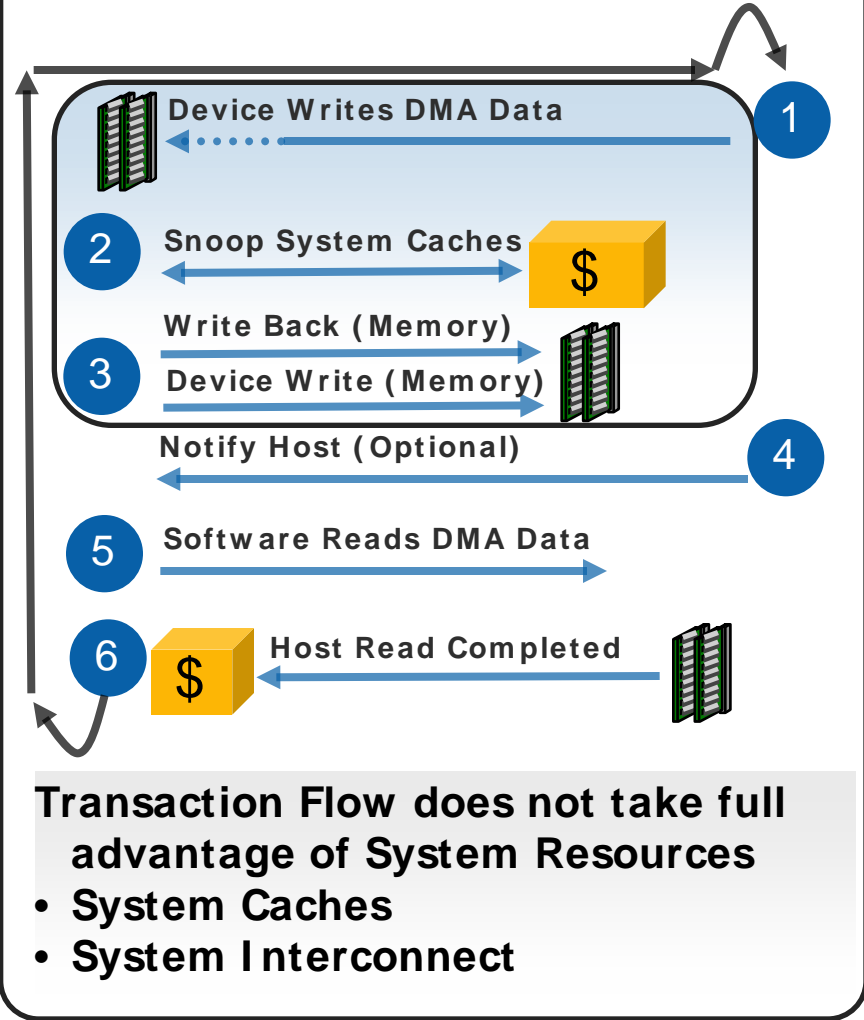


**Provides stronger coupling between Host Cache/Memory hierarchy and IO**

# Basic Device Writes

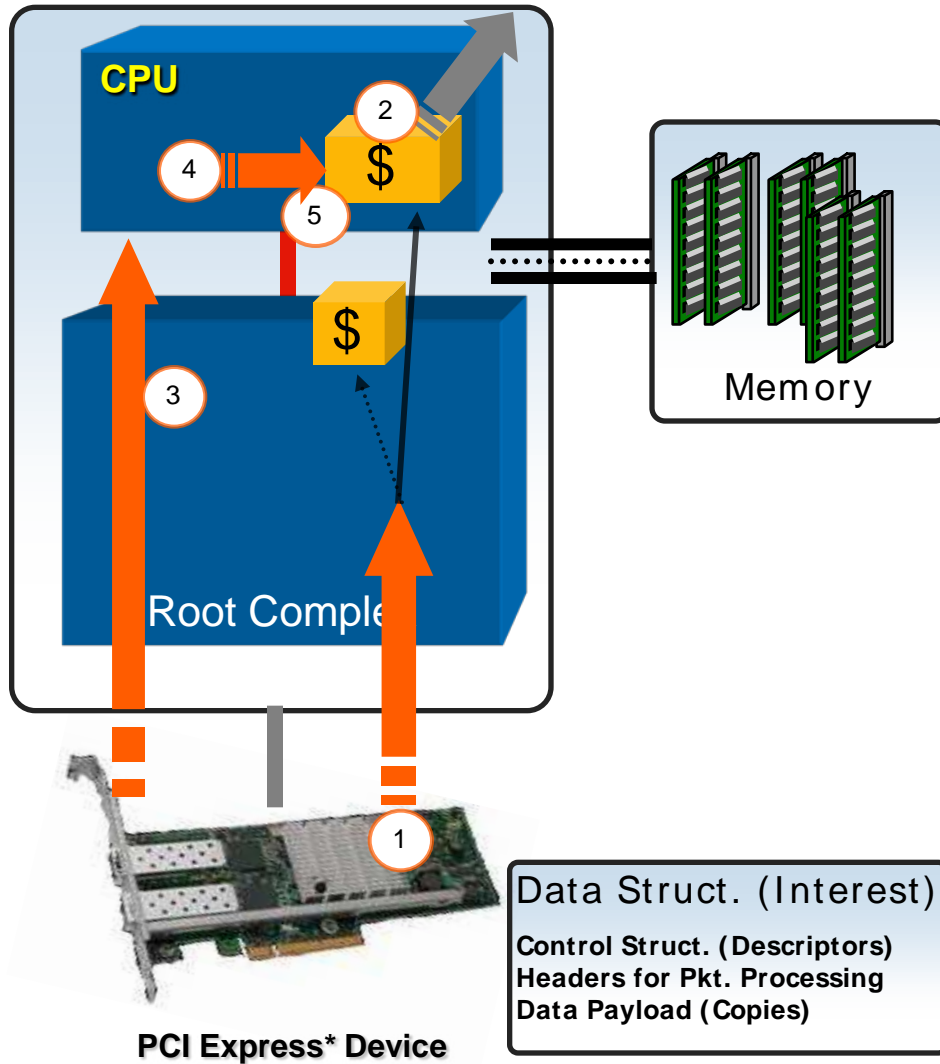


## Device Writes Host Reads

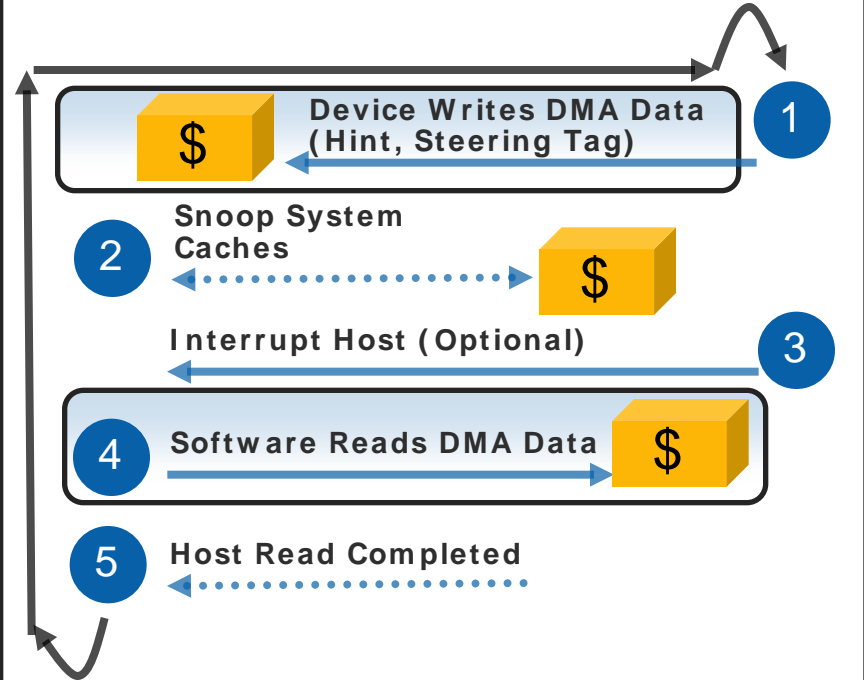




# Device Writes with TPH



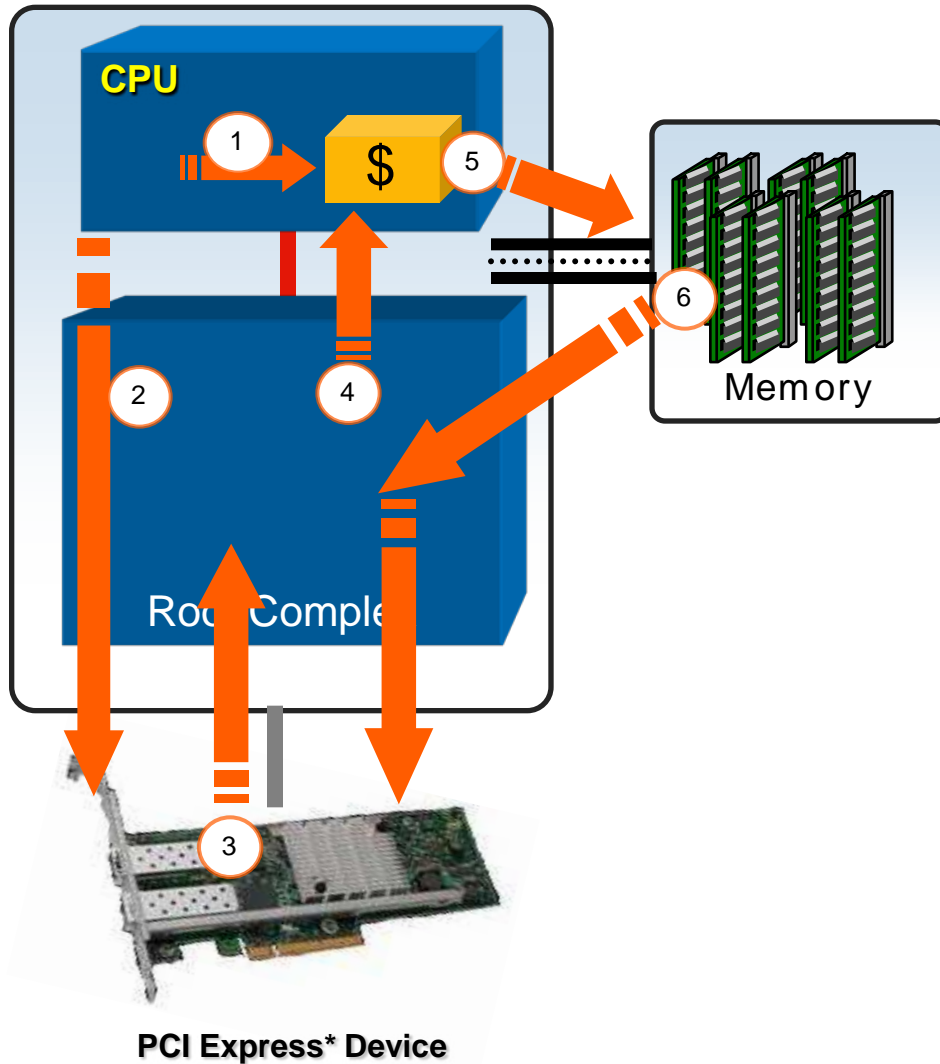
## Device Writes Host Reads



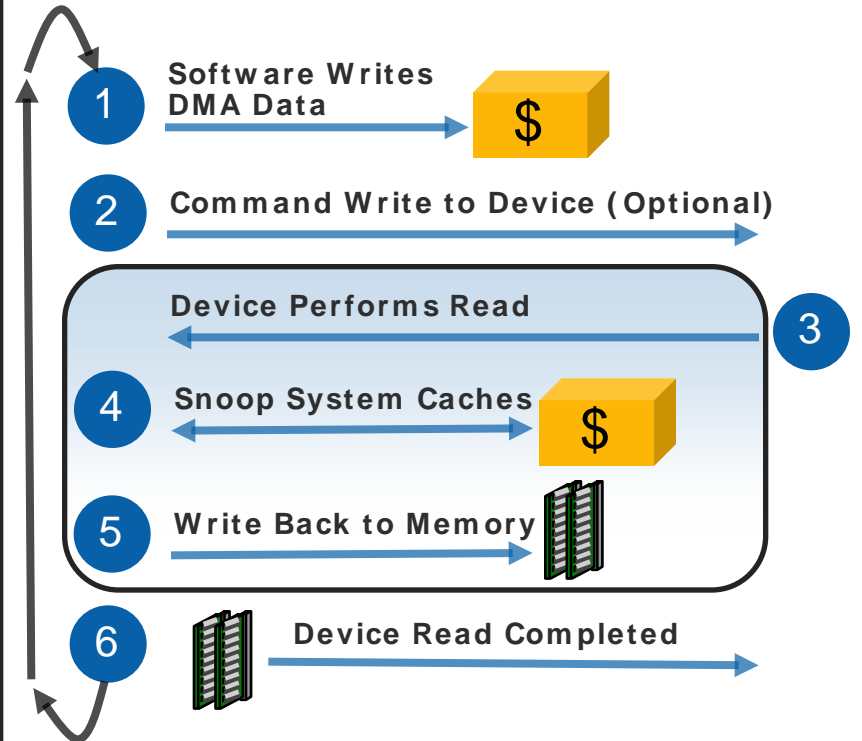
### Effective Use of System Resources

- Reduce Access latency to system memory
- Reduce Memory & system interconnect BW & Power

# Basic Device Reads



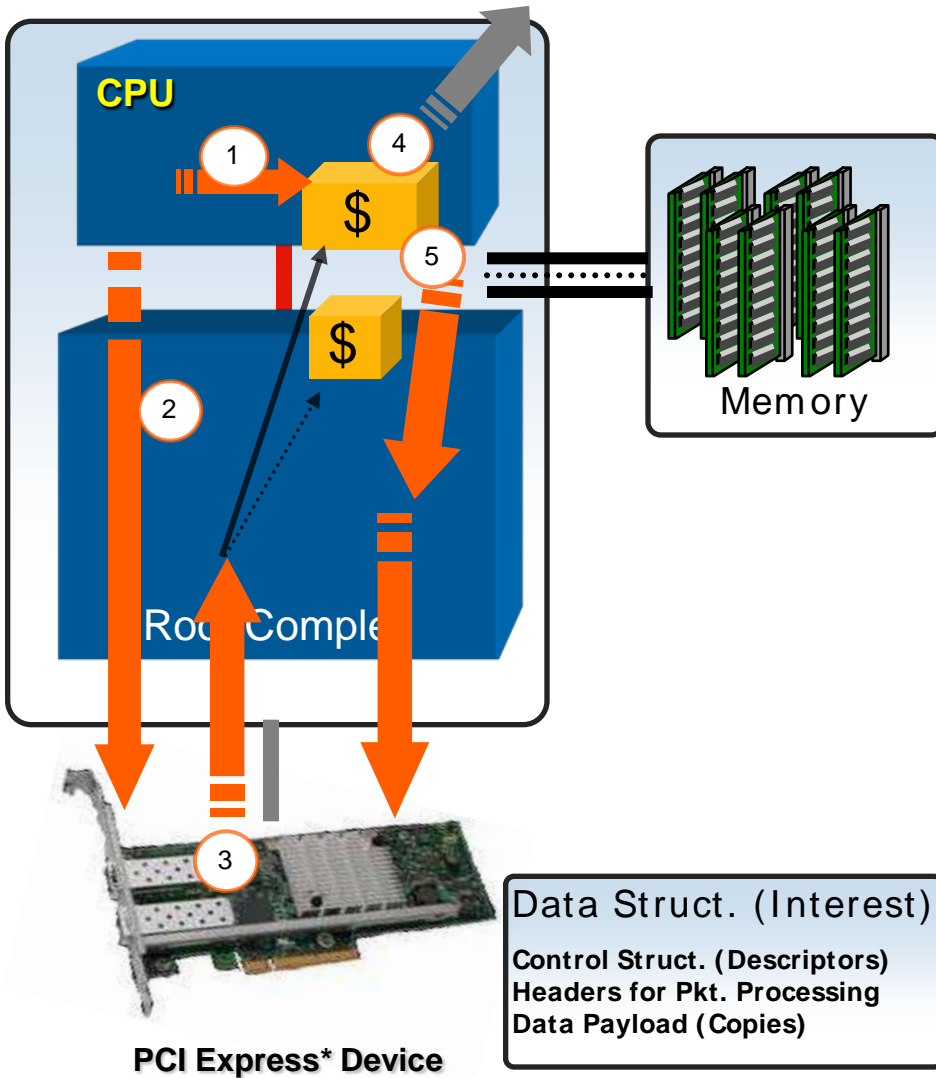
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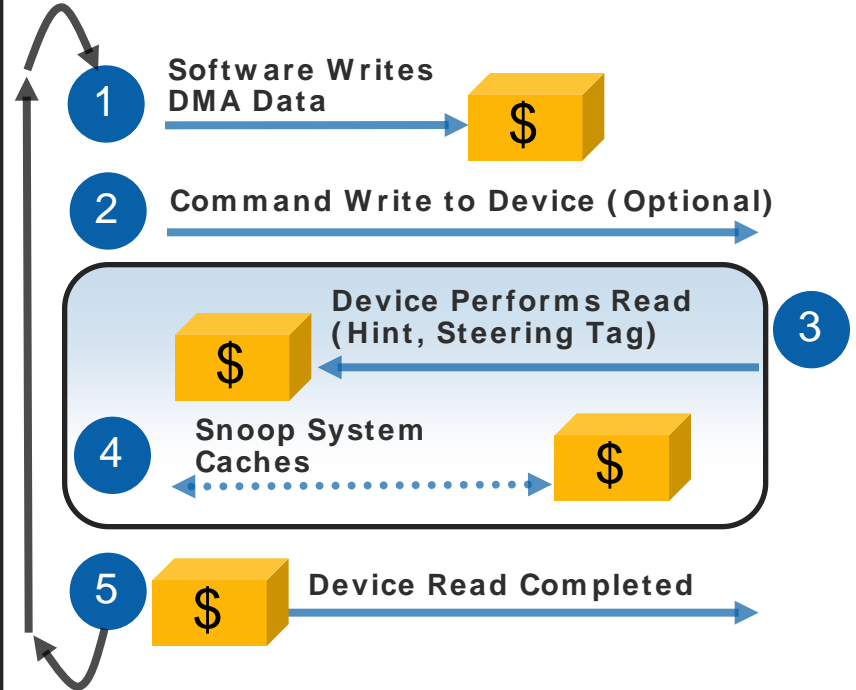
Transaction flow does not take full advantage of System Resources

- System Caches
- System Interconnect

# Device Reads with TPH



## Host Writes Device Reads

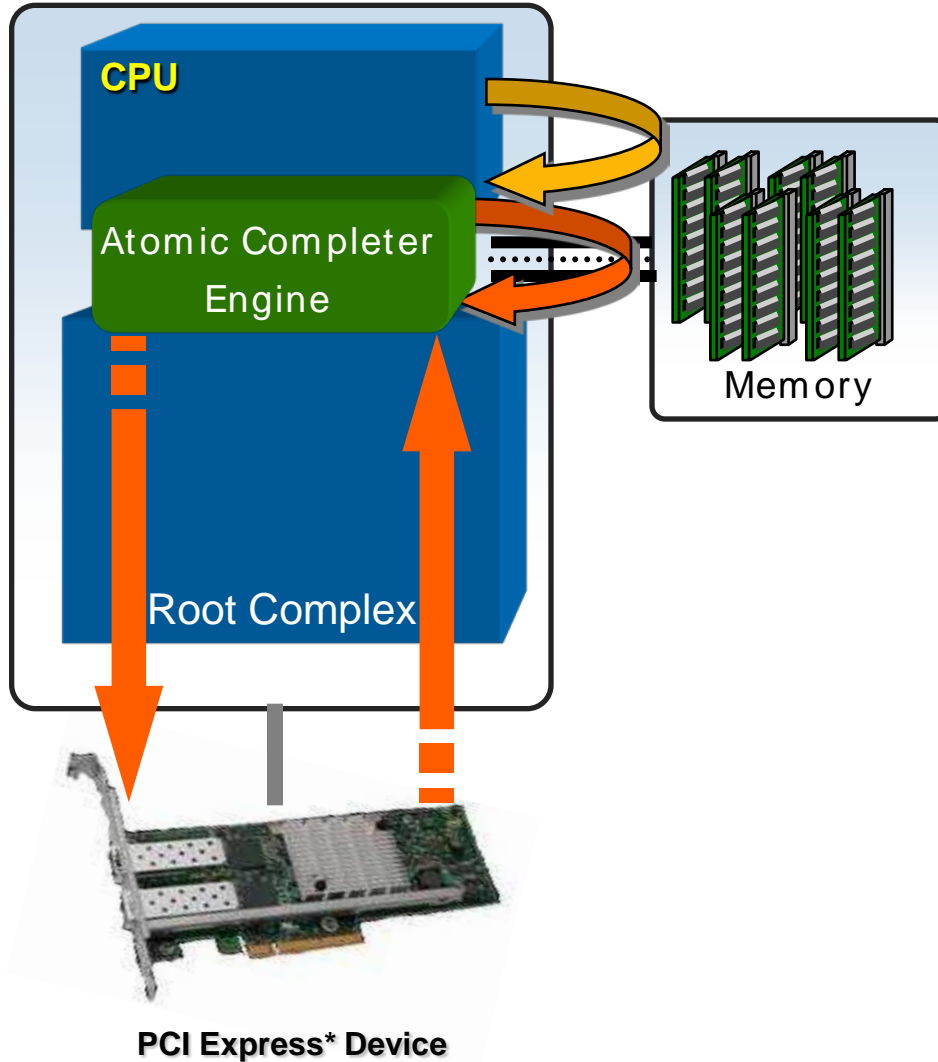


### Effective Use of System Resources

- Reduce Access latency to system memory
- Reduce Memory & system interconnect BW & Power

# Atomic Operations (AtomicOps)

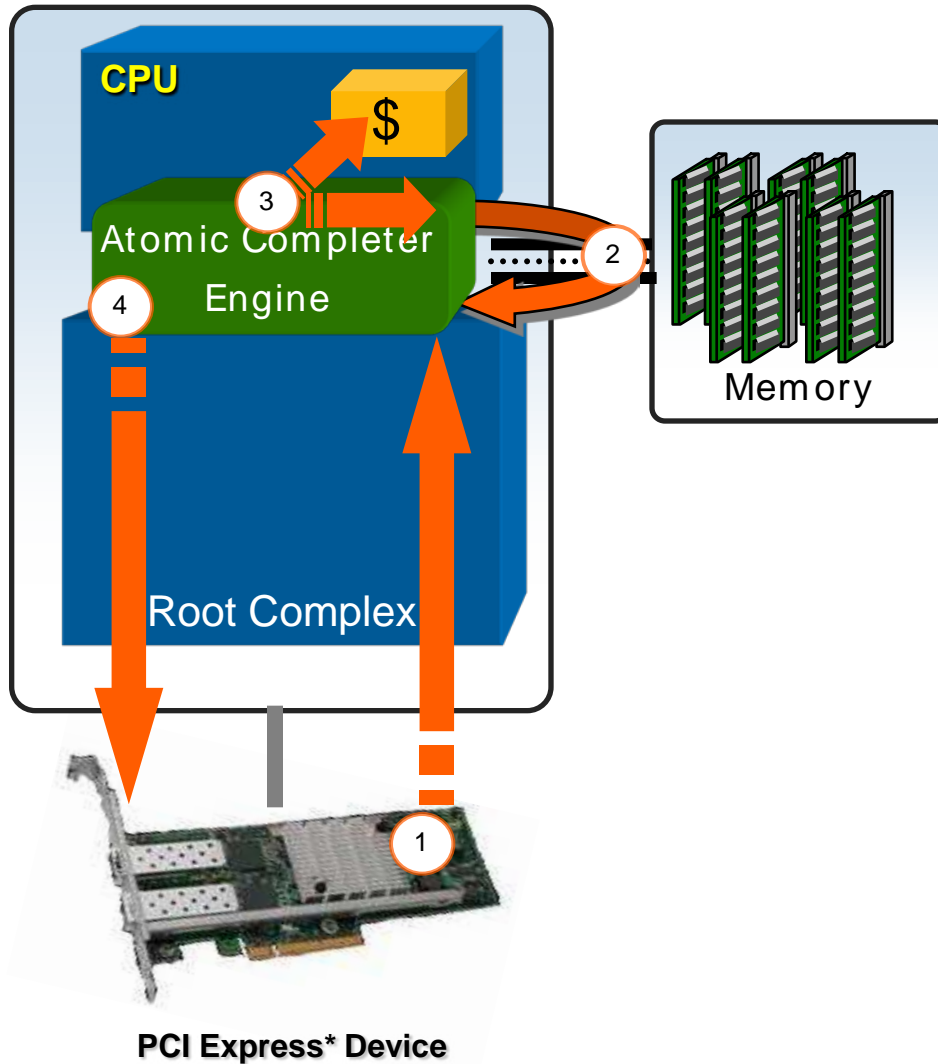
# Synchronization



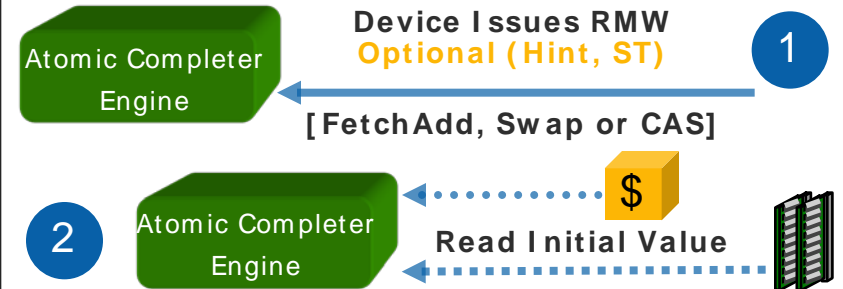
## Atomic Read-Modify-Write

- **Atomic transaction support for Host update of main memory exists today**
  - Useful for synchronization without interrupts
  - Rich library of proven algorithms in this area
- **Benefit in extending existing inter-processor primitives for data sharing/ synchronization to PCIe interconnect domain**
  - Low overhead critical sections
  - Non-Blocking algorithms for managing data structures e.g. Task lists
  - Lock-Free Statistics e.g. counter updates
- **Improve existing application performance**
  - Faster packet arrival rates create demand for faster synchronization
- **Emerging applications benefit from Atomic RMW**
  - Multiple Producer – Multiple Consumer support
  - Example: Math, Visualization, Content Processing etc

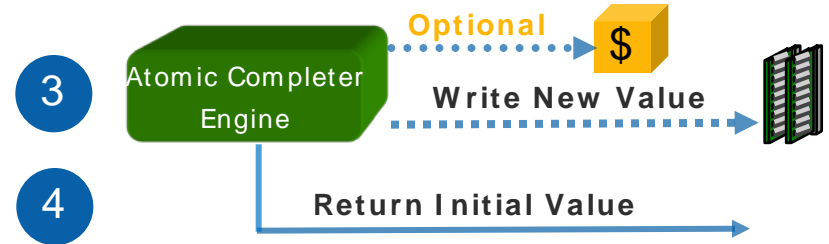
# Atomic Read-Modify-Write (RMW)



## Atomic RMW Operation



Request	Description
FetchAdd	$\text{Data}(\text{Addr}) = \text{Data}(\text{Addr}) + \text{AddData}$
Swap	$\text{Data}(\text{Addr}) = \text{SwapData}$
CAS	If (CompareData == Data(Addr)) then Data(Addr) = SwapData



# Power Management Enhancements

Dynamic Power Allocation(DPA)

Optimized Buffer Flush (OBFF)

Latency Tolerance Reporting (LTR)





# Dynamic Power Allocation

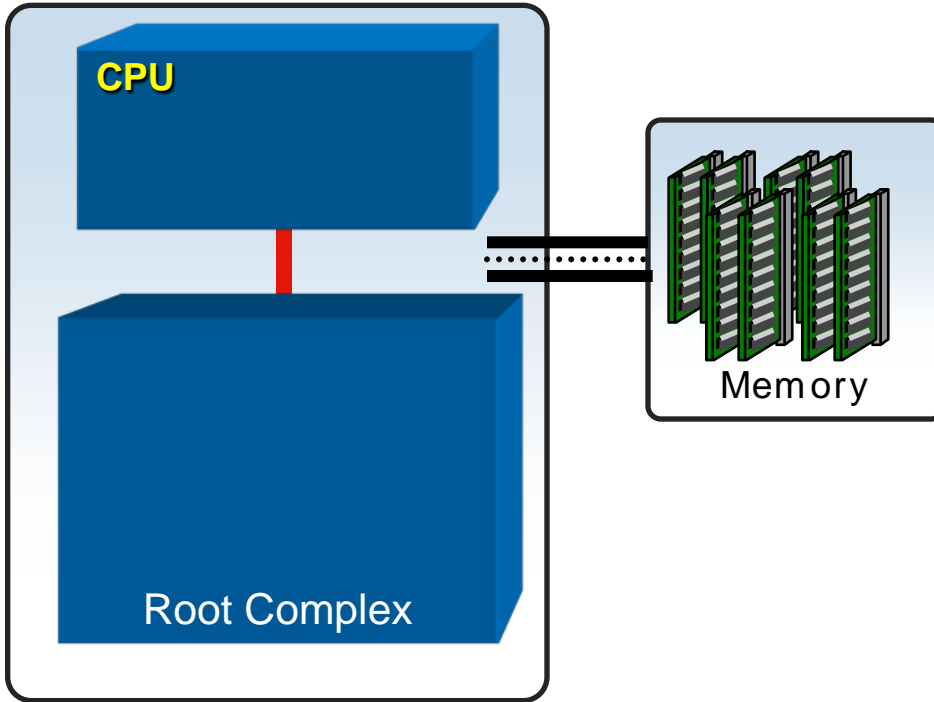
## Background

- **PCI e 1.x provided standard Device & Link-level Power Management**
- **PCI e 2.0 adds mechanisms for dynamic scaling of Link width/ speed**
- **No architected mechanism for dynamic control of device thermal/ power budgets**

## Problem Statement

- **Devices are increasingly higher consumers of system power & thermal budget**
  - Emerging 300W Add-In Cards
- **New Customer & Regulatory Operating Requirements**
  - On-going Industry wide efforts e.g. ENERGY STAR\* Compliance
  - Battery Life/Enclosure Power Management
    - Mobile, Servers & Embedded Platforms

# Dynamic Power Allocation (DPA)



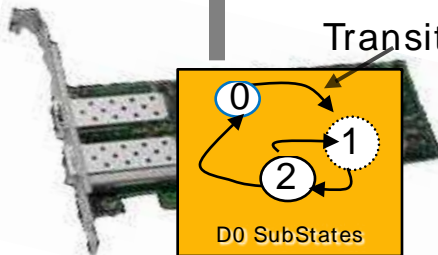
## DPA Capability

- **Extend Existing PCI Device PM to provide Active (D0) substates**
  - Up to 32 substates supported
- **Dynamic Control of D0 Active Substates**

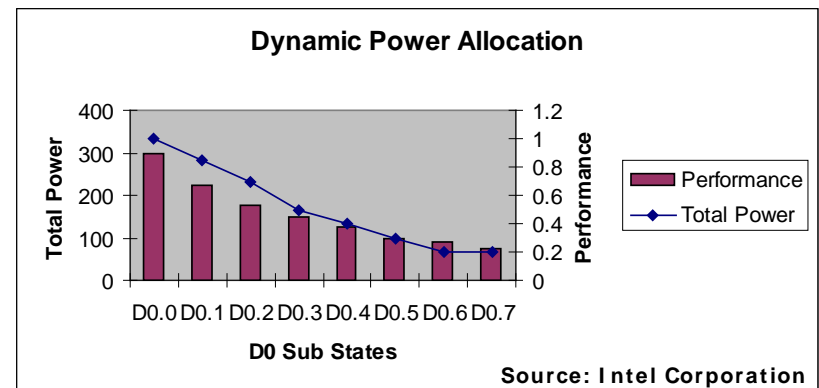
## Benefits

- **Platform Cost Reduction**
  - Pwr/Thermal Management
- **Platform Optimizations**
  - Battery Life (Mobile)/Power(Servers)

Software Managed Transitions



PCI Express\* Device



Source: Intel Corporation

**Enables New Platform Level Flexibility in Power/Thermal Resource Management**



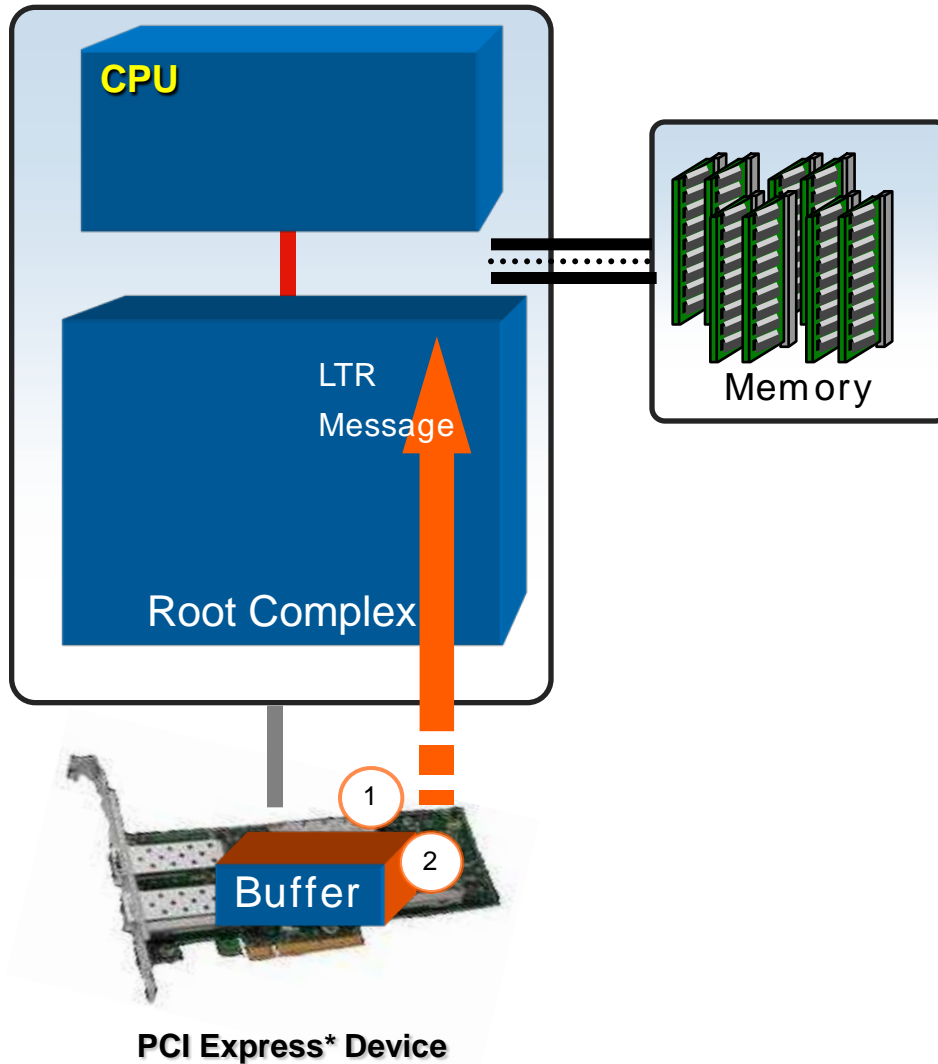
# Latency Tolerance Reporting

Problem: Current Platforms PM policies guesstimate when devices are idle (e.g. w/inactivity timers)

- **Guessing wrong can cause performance issues, or even HW failures**
- **Worst case: PM disabled to allow functionality at cost to power**
- **Even best case not good – reluctance to power down leaves some PM opportunities on the table**
  - Tough balancing act between performance / functionality and power

Wanted: Mechanism for platform to tune PM based on actual device service requirements

# Latency Tolerance Reporting (LTR)



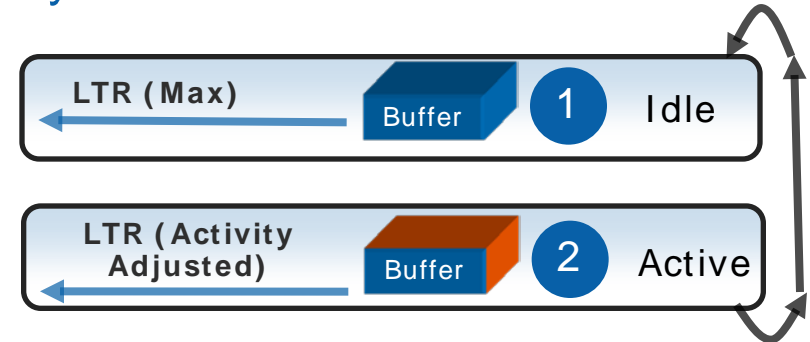
## LTR Mechanism

- **PCIe Message sent by Endpoint with tolerable latency**
  - Capability to report both snoop & non-snoop values
  - “Terminate at Receiver” routing, MFD & Switch send aggregated message

## Benefits

- **Provides Device Benefit: Dynamically tune platform PM state as a function of Device activity level**
- **Platform benefit: Enables greater power savings without impact to performance/ functionality**

## Dynamic LTR



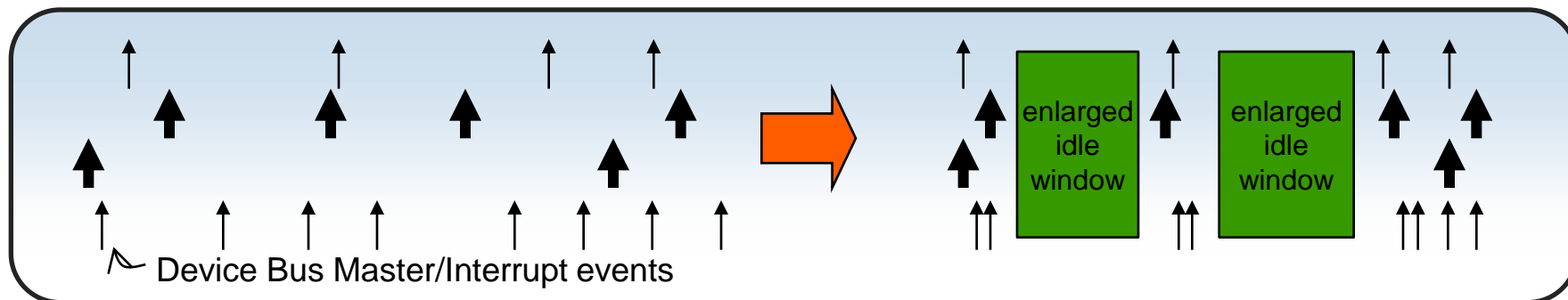
LTR enables dynamic power vs. performance tradeoffs at minimal cost impact



# Optimized Buffer Flush/ Fill

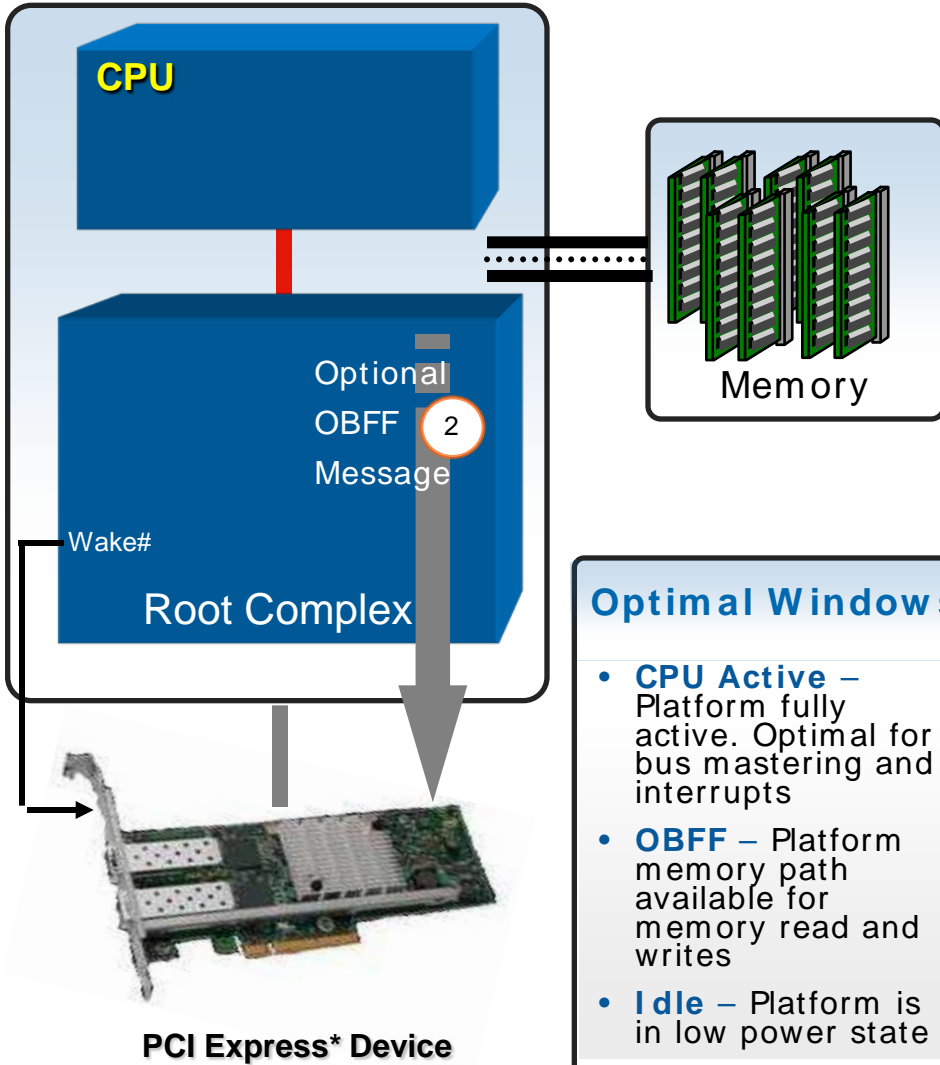
Problem: Devices do not know power state of central resources

- “Asynchronous” device activity prevents optimal power management of memory, CPU, RC internals by idle window fragmentation
- Premise: If devices knew when to talk, most could easily optimize their Request patterns
  - Result: System would stay in lower power states for longer periods of time with no impact on overall performance
- **Optimized Buffer Flush/ Fill (OBFF) - a mechanism for broadcasting PM hint to device**



Wanted: Mechanism for Align Device Activity with Platform PM events

# Optimized Buffer Flush/ Fill (OBFF)



## OBFF

- Notify all Endpoints of optimal windows with minimal power impact

Solution1: When possible, use WAKE# with new wire semantics

Solution2: WAKE# not available – Use PCIe Message

## Optimal Windows

- **CPU Active** – Platform fully active. Optimal for bus mastering and interrupts
- **OBFF** – Platform memory path available for memory read and writes
- **Idle** – Platform is in low power state

## WAKE# Waveforms

### Transition Event

### WAKE#

Idle → OBFF .....



Idle → CPU Active .....



OBFF/CPU Active → Idle .....



OBFF → CPU Active .....



CPU Active → OBFF .....



Greatest Potential Improvement When Implemented by All Platform Devices



# Other Protocol Enhancements

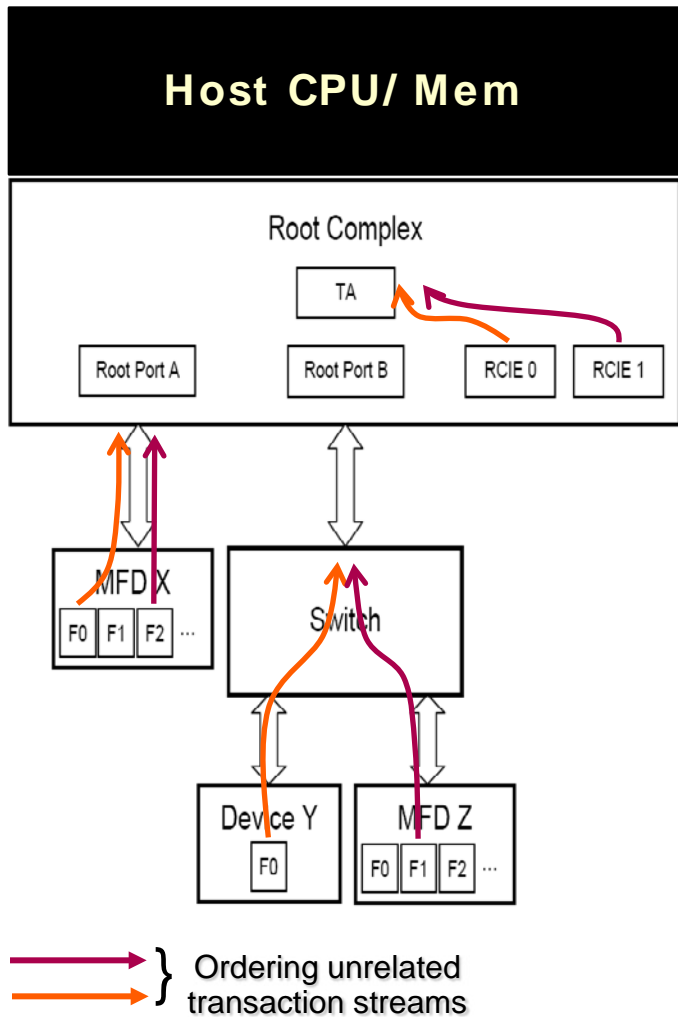
**ID-based Transaction Ordering**

**IO Page Fault Mechanism**

**Resizable BAR**

**Multicast**

# Transaction Ordering Enhancement



- Background:

- Strong ordering == unnecessary stalls
- Transactions from different Requestors carry different IDs

- Feature:

- New Transaction Attribute bit to indicate ID-based ordering relaxation
  - Permission to reorder transactions between different ID streams
- **Applies to unrelated streams within:**
  - MF Devices, Root Complex, Switches

- Benefits:

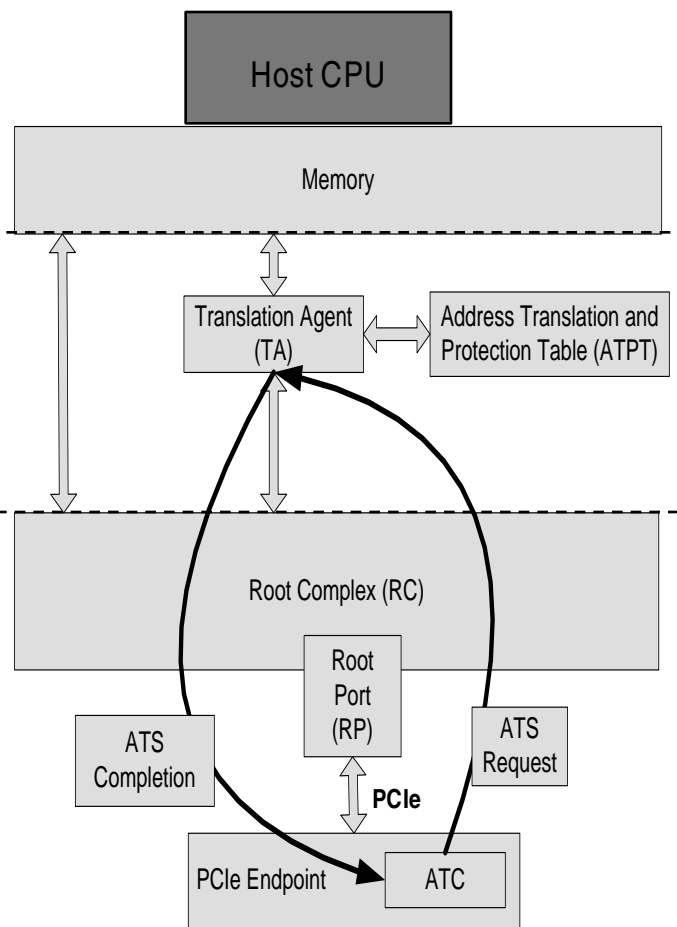
- Improves latency/ power/ BW

Reduces transaction latencies in the system.





# I/O Page Fault Mechanism



- Background:

- Emerging trend: Platform Virtualization
- Increases pressure on memory resources making page “pinning” very expensive

- Feature:

- Built upon PCIe Address Translation Services (ATS) Mechanism
- Notify I/O devices when I/O page faults occur
  - Device pause/resume on page faults
  - Faulted pages requested to be made available

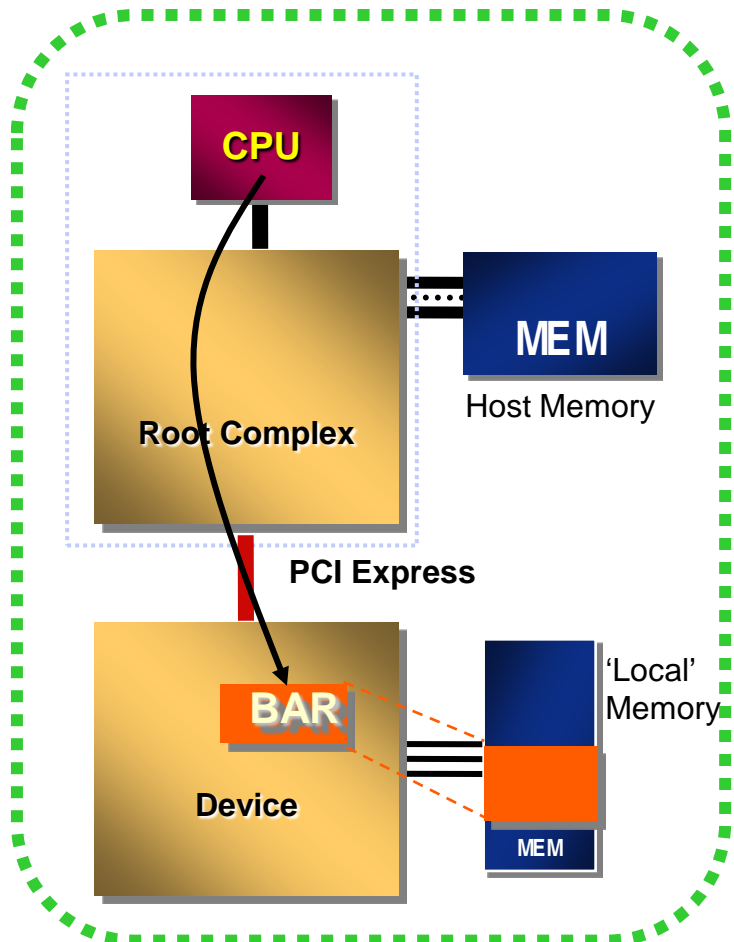
- Benefits:

- OS/ Hypervisor gets ability to maintain overall system performance

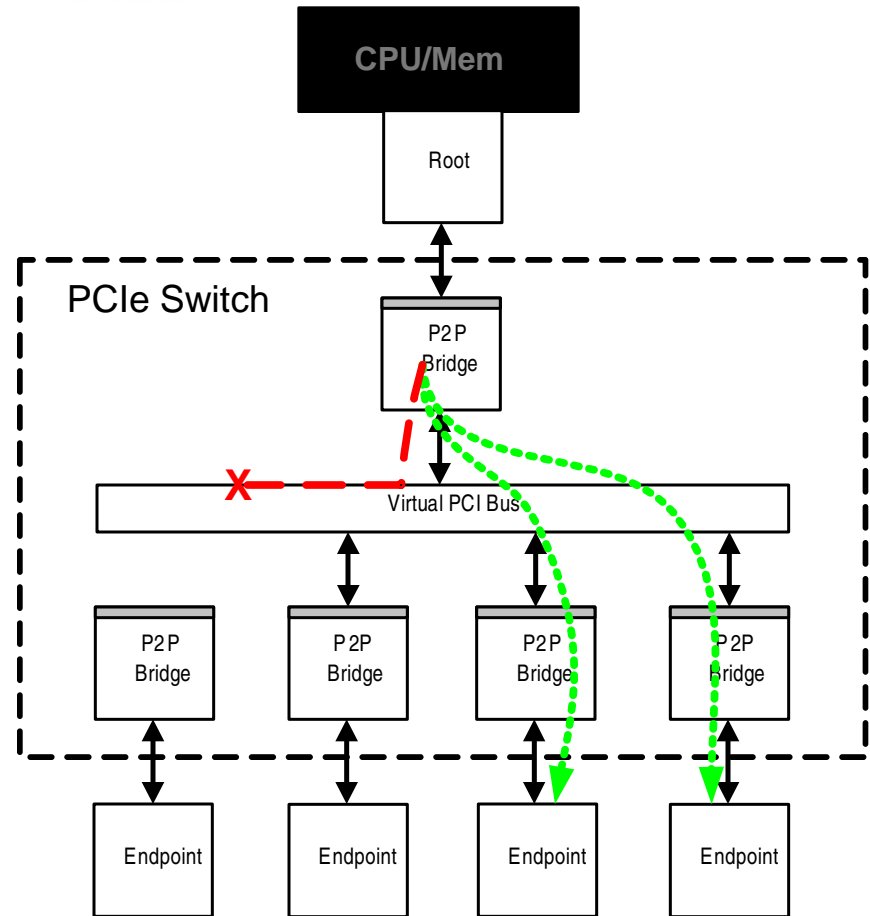
Critical for future I/O Virtualization application scaling.



# Resizable BAR & Multicast



*BAR = Base Address Register – PCI mechanism for mapping device memory into sys. address space*



**—** PCIe Standard Address Route

**- - -** Multicast Address Route

**Improved platform address space management -- solves current problems with gfx/accel**

**Multicast provides perf. scaling of existing apps (e.g. multi Gfx) -- opens new usages for PCIe in embedded space**

# Summary

- **8.0 GT/s silicon design is challenging but achievable**
- **Double B/W: Encoding efficiency 1.25 X data rate 1.6 = 2X**
- **Next Generation PCIe Protocol Extensions Deliver**
  - Energy Efficient Performance,
  - Software Model Improvements and
  - Architecture Scalability
- **Specification Status:**
  - Rev 0.5 spec delivered to PCI SIG in Q1'09
  - Rev 0.7 targeting Sept. '09 & Rev 0.9 early Q1'10

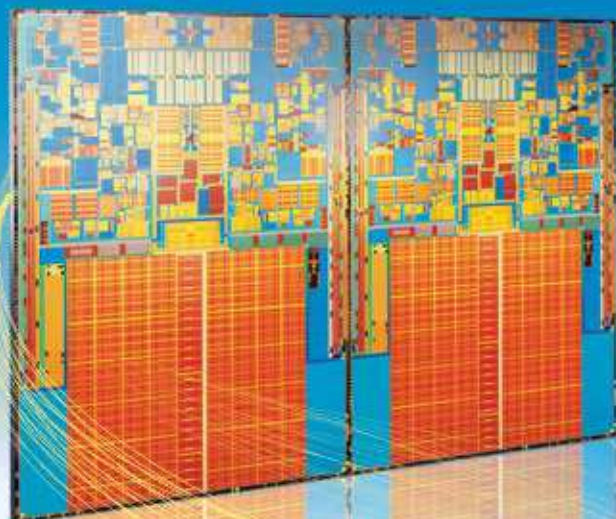
***Continuous Improvement: Doubling Bandwidth & Improving Capabilities Every 3-4 Years!***

# Call to Action & References

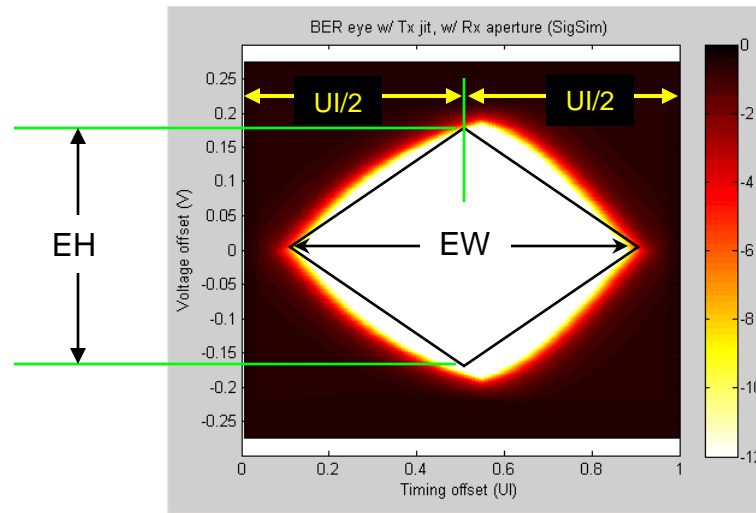
- **Contribute to the evolution of PCI Express architecture**
  - Review and provide feedback on PCIe 3.0 specs
  - Innovate and differentiate your products with PCIe 3.0 industry standard
- **Visit:**
  - [www.pcisig.com](http://www.pcisig.com) for PCI Express specification updates
  - [http://download.intel.com/technology/pciexpress/devnet/docs/PCIe3\\_Accelerator-Features\\_WP.pdf](http://download.intel.com/technology/pciexpress/devnet/docs/PCIe3_Accelerator-Features_WP.pdf) for white-paper on PCIe Accelerator Features



# *Backup*



# Example of a Eye As Seen At Receiver Input Latch



Eye aperture defines  $T_j$  at  $10^{-12}$

Eye margins reflect CDR tracking and Rx equalization



# Scrambling vs. 8b/10b coding

- **8GT/s uses scrambled data to improve signaling efficiency over 8b10b encoding used in 2.5GT/s and 5GT/s, yielding 2x payload data rate wrt. 5 GT/s**
- **Unlike 8b10b a maximal length PRBS generated by an LFSR does not preserve DC balance**
  - The average voltage level over a constant period of time varies slowly based on the pattern of the PRBS
  - In an AC coupled system this creates a slowly changing differential offset that that reduces eye height
- **Different PRBS polynomials have different average run lengths through their pattern and so different peak differential offsets**
  - There exists a best case PRBS23 polynomial yielding minimum DC wander of  $\sim 4.5 \text{ mVPP}$ :  $x^{23} + x^{21} + x^{18} + x^{15} + x^7 + x^2$
- **Large number of taps tends to break up long runs of 0s or 1s (a common case)**
  - Pathological match between PRBS and data pattern have very low probability
  - Retry mechanism changes polynomial starting point to prevent pathological data pattern from failing repeatedly

# Gen3 Signaling: Error Detection & Recovery

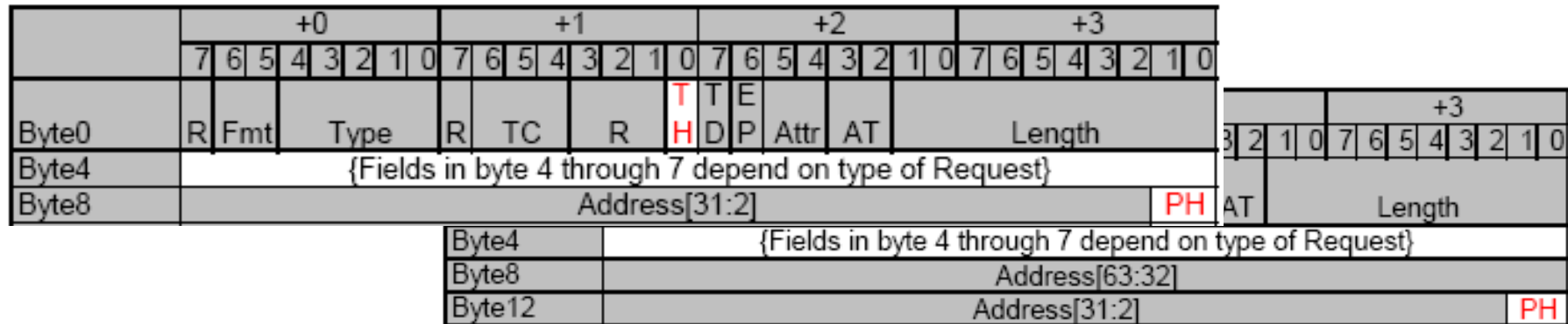
- **Framing error is detected by the physical layer**
  - The first byte of a packet is not one of the allowed sets (e.g., TLP, DLLP, LIDL)
  - Sync character is not 01 or 10
  - Same sync character not present in all lanes after deskew
  - CRC error in the length field of a TLP
  - Ordered set not one of the allowed encodings or not all lanes sending the same ordered set after deskew (if applicable)
  - 10 sync header received after 01 sync header without a marker packet in the 01 sync header OR received a marker packet in the 01 sync header and the subsequent sync header in any lane not 10
- **Any framing error requires directing LTSSM to Recovery**
  - Stop processing any received TLP/ DLLP after error until we get through Recovery
  - Block lock acquired with EIEOS
  - Scrambler reset with each EIEOS
- **Error Detection Guarantees**
  - Triple bit flip detection within each TLP/ DLLP/ IDL/ OS



# TLP Processing Hints (TPH)



# TPH Mechanism

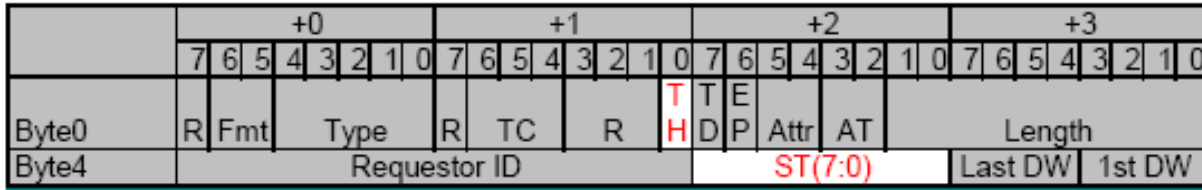


- Mechanism to provide processing hints on per TLP basis for Requests that target Memory Space**

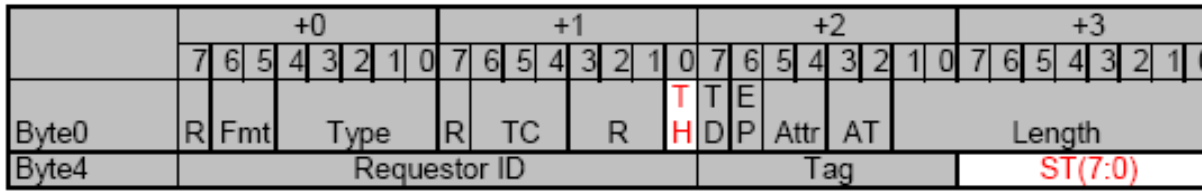
- Enable system hardware (ex: Root-Complex) to optimize on a per TLP basis
- Applicable to Memory Read/Write and Atomic Operations

PH[1:0]	Processing Hint	Usage Model
00	Bi-directional data structure	Bi-Directional data structure
01	Requestor	D*D*
10	Target	DWHR HWDR
11	Target with Priority	DWHR (Prioritized) HWDR (Prioritized)

# Steering Tag (ST)



← Memory Write TLP



← Memory Read or AtomicOperation TLPs

- **ST: 8 bits defined in header to carry System specific Steering Tag values**

- Use of Steering Tags is optional – ‘No preference’ value used to indicate no steering tag preference
- Architected Steering Table for software to program system specific steering tag values

# TPH Summary

- **Mechanism to make effective use of system fabric and improve system efficiency**
  - Reduce variability in access to system memory
  - Reduce memory & system interconnect BW & power consumption
- **Ecosystem Impact**
  - Software impact is under investigation - minimally may require software support to retrieve hints from system hardware
  - Endpoints take advantage only as needed → No cost if not used
  - Root Complex can make implementation tradeoffs
  - Minimal impact to Switches
- **Architected software discovery, identification, and control of capabilities**
  - RC support for processing hints
  - Endpoint enabling to issue hints

# **ID-Based Ordering (IDO)**

# Review: PCIe Ordering Rules

“No” entries caused by Producer/Consumer restrictions

Row Pass Column?		Posted Request (Col 2)	Non-Posted Request		Completion (Col 5)
			Read Request (Col 3)	NPR with Data (Col 4)	
Posted Request (Row A)		a) No b) Y/N	Yes	Yes	a) Y/N b) Yes
Non-Posted Request	Read Request (Row B)	No	Y/N	Y/N	Y/N
	NPR with Data (Row C)	No	Y/N	Y/N	Y/N
Completion (Row D)		a) No b) Y/N	Yes	Yes	a) Y/N b) No

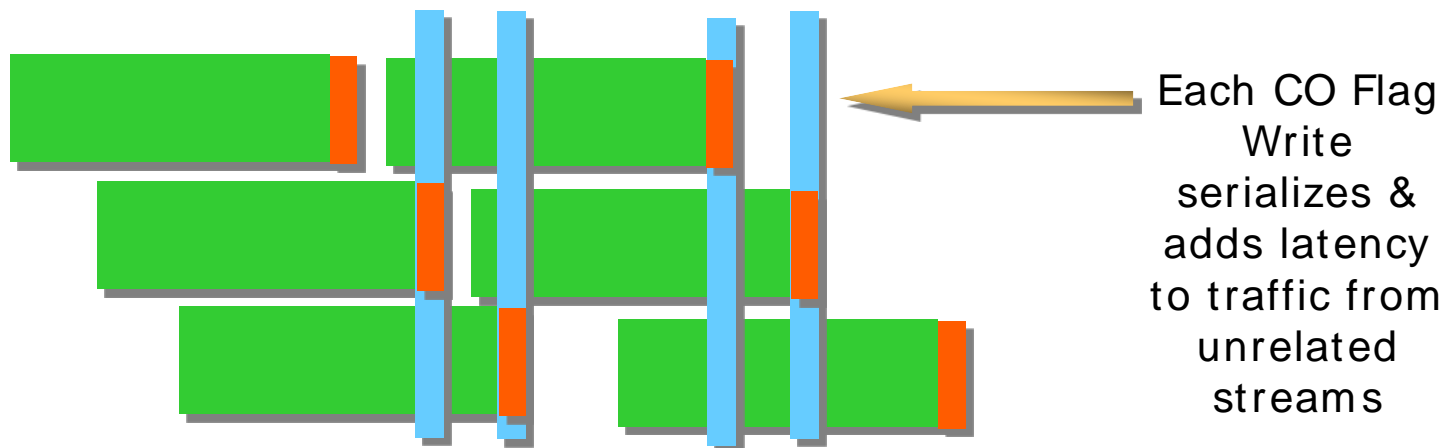
Table is based on new 2.0 errata!

“Yes” entries are required for deadlock avoidance

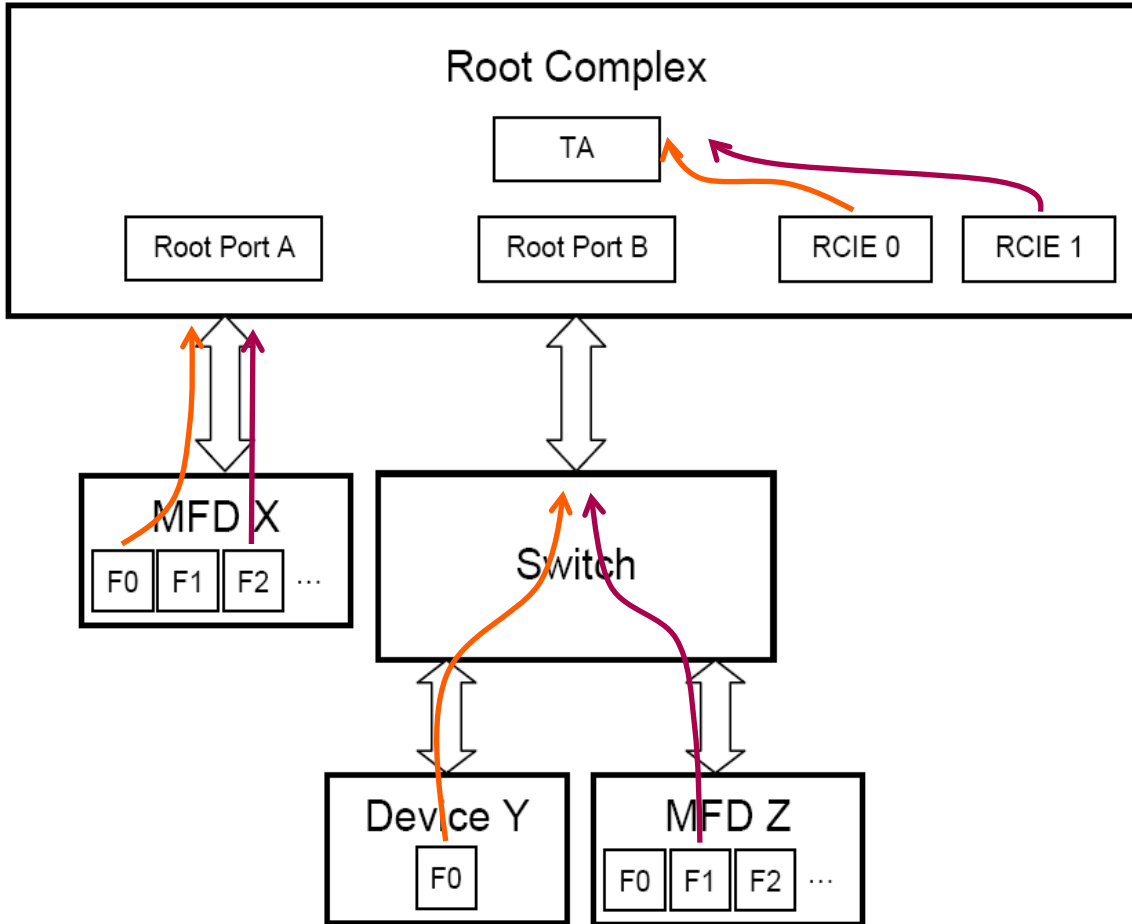
- **Maximum theoretical flexibility: All entries are “Y/ N”**
- **Traditional Relaxed Ordering (RO) enables A2 & D2 “Y/ N” cases**
  - AtomicOps ECR defines an RO-enabled C2 “Y/N” case
- **ID-Based Ordering (IDO) enables A2, B2, C2, & D2 “Y/ N” cases**

# Motivation

- **RO works well for single-stream models where a data buffer is written once, consumed, and then recycled**
  - Not OK for buffers that will be written more than once because writes are not guaranteed to complete in order issued
  - Does not take advantage of the fact that ordering doesn't need to be enforced between unrelated streams
- **Conventional Ordering (CO) can cause significant stalls**
  - Observed stalls in the 10's to 100's of ns are seen
  - Worst case behavior may see such stalls repeatedly for a Request stream
- **Consider case of NIC or disk controller with multiple streams of writes:**



# IDO: Perf Optimizations for Unrelated TLP Streams

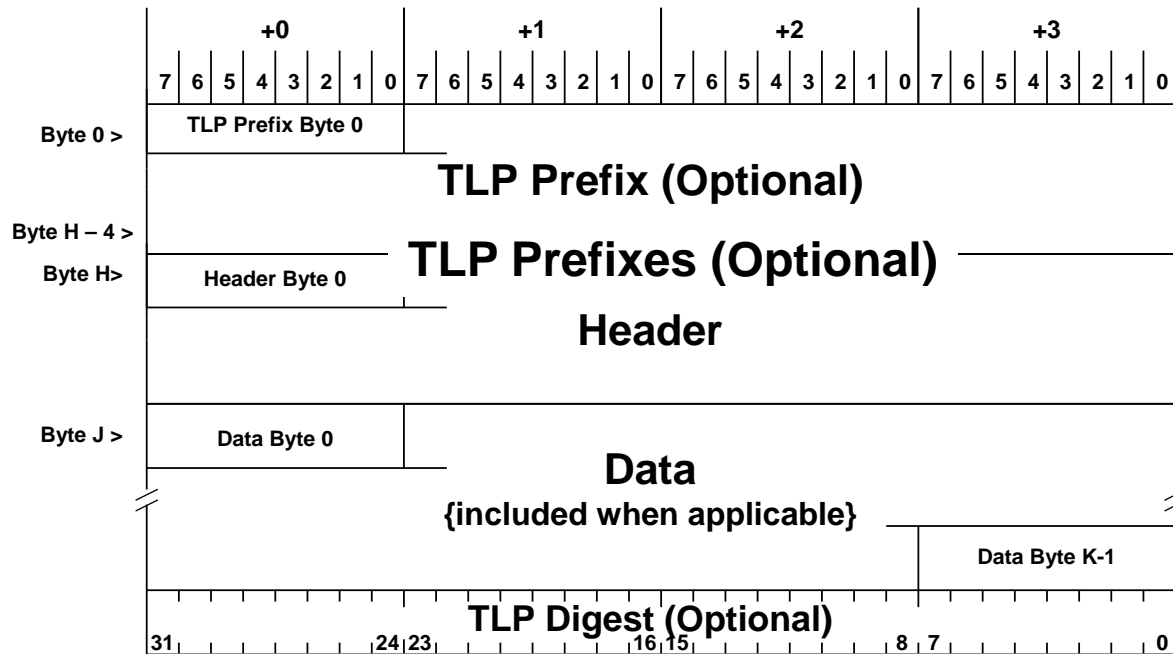


- **TLP Stream: a set of TLPs that all have the same originator**
- **Optimizations possible for unrelated TLP Streams, notably with:**
  - Multi-Function device (MFD) / Root Port Direct Connect
  - Switched Environments
  - Multiple RC Integrated Endpoints (RCIEs)
- **IDO permits passing between TLPs in different streams**
- **Particularly beneficial when a Translation Agent (TA) stalls TLP streams temporarily**



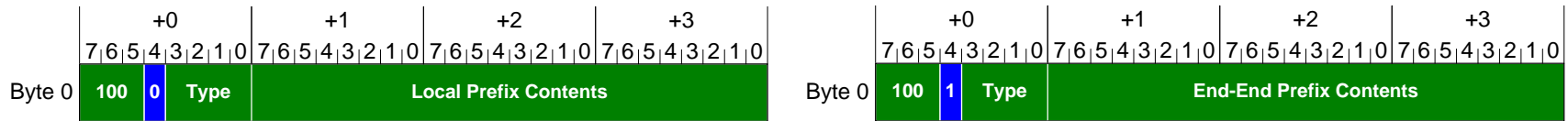
# TLP Prefix

# Motivation



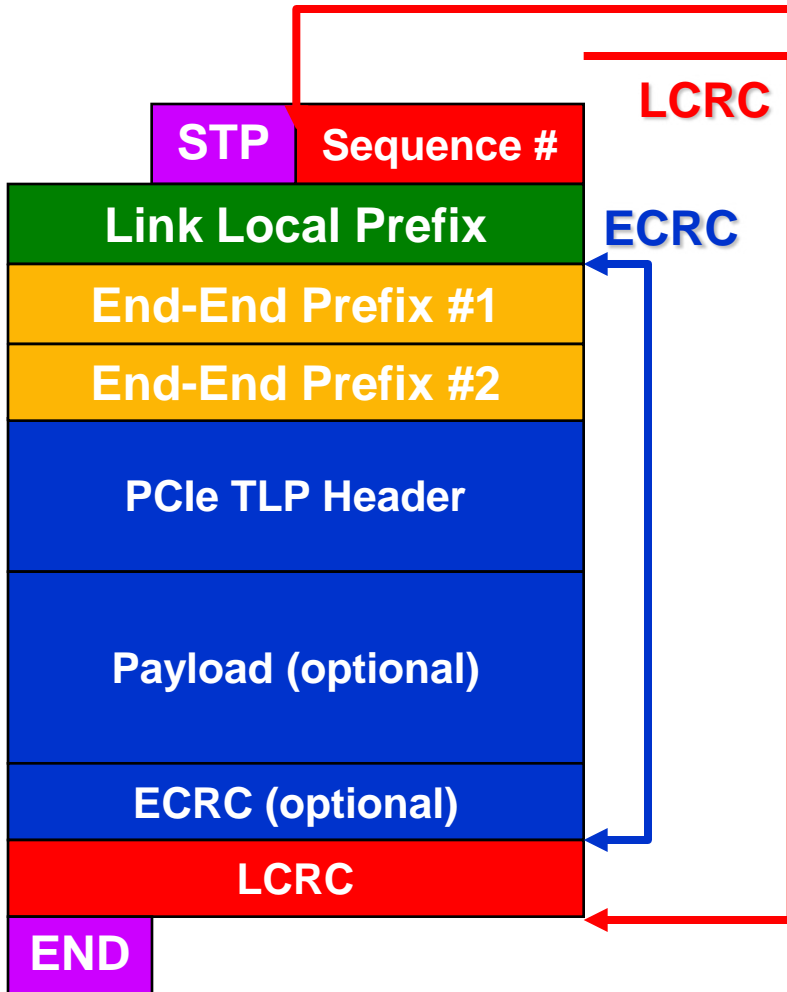
- **Emerging usage models require increase in header size to carry new information**
  - Example: Multi-Root IOV, Extended TPH
- **TLP Prefix mechanism extends the header sizes by adding DWORDs to the front of headers**

# Prefix Encoding



- **Base TLP Prefix Size – 1 DW**
  - Appended to TLP headers
- **TLP Prefixes can stacked or repeated**
  - More than one TLP Prefix supported
- **Link Local – Where routing elements may process the TLP for routing or other purposes.**
  - Only usable when both ends understand and are enabled to handle link local TLP Prefix
  - ECRC not applicable
- **End-End TLP Prefix**
  - Requires support between the Requester, Completer and routing elements
  - End-End TLP Prefix not required to but is permitted to be protected by ECRC
    - If underlying Base TLP is protected by ECRC then End-End TLP Prefix is also protected by ECRC
  - Upper bound of 4DWORDs (16 Bytes) for End-End TLP Prefix
- **Fmt field grows to 3 bits**
  - New error behavior defined
  - Undefined Fmt and/or Type values results in Malformed TLP
  - “Extended Fmt Field Supported” capability bit indicates support for 3 bit Fmt
    - Support is recommended for all components (independent of Prefix support)

# Stacked Prefix Example:



- **Link Local is first**
  - Starts at 0
  - Type<sub>L1</sub>
- **End-End # 1 follows Link Local**
  - Starts at 4
  - Type<sub>E1</sub>
- **End-End # 2 follows End-End # 1**
  - Starts at 8
  - Type<sub>E2</sub>
- **PCIe Header follows End-End # 2**
  - Starts at 12
- **Switch routes using Link Local and PCIe Header**
  - ... and possibly additional Link Local DWORDs
    - if more extension bits needed
  - Malformed TLP if don't understand
- **Switch forwards End-End Prefixes unaltered**
  - End-End Prefixes do not affect routing
  - Up to 4 DWORDs (16 Bytes) of End-End Prefix
- **End-End Prefixes are optional**
  - Different End-End Prefixes sequence are unordered
    - affects ECRC but does not affect meaning
  - Repeated End-End Prefix sequence must be ordered
    - e.g. 1<sup>st</sup> Extended TPH vs. 2<sup>nd</sup> Extended TPH attribute
    - meaning of this is defined by each End-End Prefix

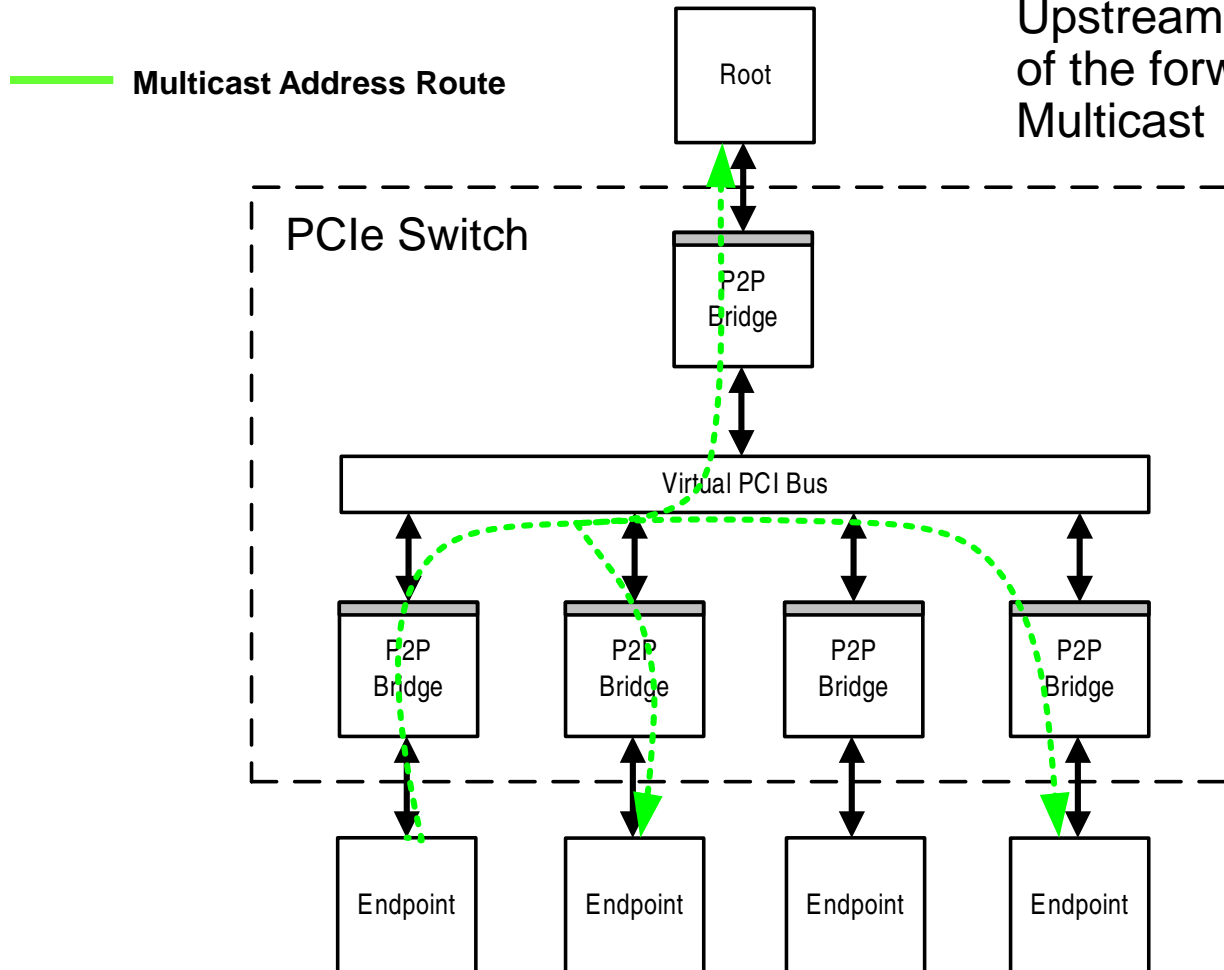
# Multicast

# Multicast Motivation & Mechanism Basics

- **Several key applications benefit from Multicast**
  - Communications backplane (e.g. route table updates, support of IP Multicast)
  - Storage (e.g., mirroring, RAID)
  - Multi-headed graphics
- **PCIe architecture extended to support address-based Multicast**
  - New Multicast BAR to define Multicast address space
  - New Multicast Capability structure to configure routing elements and Endpoints for Multicast address decode and routing
  - New Multicast Overlay mechanism in Egress Ports allow Endpoints to receive Multicast TLPs without requiring Endpoint Multicast Capability structure
- **Supports only Posted, address-routed transactions (e.g., Memory Writes)**
  - Supports both RCs and EPs as both targets and initiators
  - Compatible with systems employing Address Translation Services (ATS) and Access Control Services (ACS)
  - Multicast capability permitted at any point in a PCIe hierarchy

# Multicast Example

- Address route Upstream—Upstream Port must be part of the forwarding Ports for Multicast



# Multicast Memory Space

